# ARMY TM 11-7025-221-20 AIR FORCE T.O. 31S5-2G-252 MARINE CORPS TM-08467A-2012 

ORGANIZATIONAL MAINTENANCE MANUAL


MULTIPLEXER, DIGITAL TD-1337(V)1/G (NSN 7025-01-1 12-6311)
MULTIPLEXER, DIGITAL TD-1337(V)2/G (NSN 7025-01-112-6310)
MULTIPLEXER, DIGITAL TD-1337(V)3/G (NSN 7025-01-1 12-6312)
MULTIPLEXER, DIGITAL TD-1337(V)4/G (NSN 7025-01-127-7020)


DEPARTMENTS OF THE ARMY, THE AIR FORCE, AND THE MARINE CORPS

## WARNING

- TD-1337(V)/G weighs approximately 62 pounds. Have another person help you lift and support it to prevent injury to yourself and others,
- When locks on slides are bypassed, there are no mechanical restraints to prevent TD-1337(V)/G from rolling out of slides and falling. If locks are bypassed, use a second person to help you support TD-1337(V)/G to prevent possible injury to yourself and others.
- High voltage is applied to TD-1337(V)/G when rack power is on. To prevent a serious shock hazard that could result in DEATH or SERIOUS INJURY, turn off rack power when removing or installing a TD-1337(V)/G.
- High voltage is applied to front panel when rack power is on. To prevent a serious shock hazard that could result in DEATH or SERIOUS INJURY, turn off rack power when removing or installing a front panel.

FOR ARTIFICIAL RESPIRATION, REFER TO FM 21-11. IS THE VICTIM OF ELECTRICAL SHOCK

1DO NOT TRY TO PULL OR GRAB THE INDIVIDUAL IF POSSIBLE , TURN OFF THE ELECTRICAL POWER

3 IF YOU CANNOT TURN OFF THE ELECTRICAL POWER, PULL, PUSH, OR LIFT THE PERSON TO SAFETY USING A WOODEN POLE OR A ROPE OR SOME OTHER INSULATING MATERIAL

4SEND FOR HELP AS SOON AS POSSIBLE

5AFTER THE INJURED PERSON IS FREE OF CONTACT WITH THE SOURCE OF ELECTRICAL SHOCK, MOVE THE PERSON A SHORT DISTANCE AWAY AND IMMEDIATELY START ARTIFICIAL RESUSCITATION

# Organizational Maintenance Manual MULTIPLEXER, DIGITAL TD-1337(V)1/G (NSN 7025-01-1 12-6311) <br> MULTIPLEXER, DIGITAL TD-1337(V)2/G <br> (NSN 7025-01-1 12-6310) <br> MULTIPLEXER, DIGITAL TD-1337(V)3/G <br> (NSN 7025-01-1 12-6312) <br> MULTIPLEXER, DIGITAL TD-1337(V)4/G <br> (NSN 7025-01-1 27-7020) 

## REPORTING ERRORS AND RECOMMENDING IMPROVEMENTS

You can help improve this manual. If you find any mistakes or if you know of a way to improve the procedures, please let us know. Mail your letter, DA Form 2028 (Recommended Changes to Publications and Blank Forms), or DA Form 2028-2 located in back of this manual direct to: Commander, US Army Communications-Electronics Command and Fort Monmouth, ATTN: DRSEL-ME-MP, Fort Monmouth, New Jersey 07703.

For Air Force, submit AFTO Form 22 (Technical Order System publication Improvement Report and Reply) in accordance with paragraph 6-5, Section VI, T.O. 00-5-1. Forward direct to prime ALC/MST.

Marine Corps Units should submit NAVMC10772.
In either case, a reply will be furnished direct to you.

|  | HOW TO USE THIS MANUAL. | Page III |
| :---: | :---: | :---: |
| CHAPTER 1 | INTRODUCTION |  |
| Section I | General Information | 1-1 |
| II | Equipment Description and Data | 1-5 |
| III | Principles of Operation | 1-15 |
| CHAPTER 2 | MAINTENANCE INSTRUCTIONS |  |
| Section | Service Upon Receipt | 2-1 |
| II | Preventive Maintenance Checks and Services | 2-11 |
| III | Troubleshooting | 2-11 |
| IV | Maintenance Procedures | 2-31 |
| V | Preparation for Storage or Shipment | 2-52 |
| APPENDIX A | REFERENCES | A-1 |
| B | MAINTENANCE ALLOCATION CHART | B-1 |
| C | EXPENDABLE SUPPLIES AND MATERIALS LIST | C-1 |
| INDEX |  | -1-1 |

## HOW TO USE THIS MANUAL

You can maintain Digital Multiplexer TD-1337(V)/G more efficiently if you become familiar with the contents of this manual.

The table of contents, preceding this page, lists 011 the sections, chapters, and appendixes in the manual. There is an alphabetical index at the back of the manual. This index lists all the types of information in the manual in alphabetical order. For example, look under " P " if you want to locate which pages in the manual contain "Plug-in card replacement instructions".

There is a quick-locate index on the front cover that shows the most used information in the manual. Each index entry shows the first page number of a section or chapter. In turn, there is an index of all the paragraphs in the section or chapter on the page listed. This type of indexing helps you to quickly locate troubleshooting or maintenance information, or other types of information described below.

- Equipment Description (page 1-5), Descriptions of the TD-1337(V)/G physical and electrical characteristics are in this section. Identification plates and stenciling on the TD-1337(V)/G are also described in this section.
- Principles of Operation (page 1-15). This section contains card-level block diagram discussions for the multiplexer and demultiplexer sections of the TD-1337(V)/G. There are separate discussions for the sections in V1/V2 models and the sections in V3/V4 models.
- Service Upon Receipt (page 2-1). Normally, the TD-1337(V)/G is installed as part of a shelter configuration. If you have to plan a TD-1337(V)/G installation, the physical and electrical interface requirements are described in this section. Unpacking instructions for a TD-1337(V)/G are in this section.


## NOTE

There are no preventive maintenance checks and services authorized for organizational maintenance.

- Troubleshooting (page 2-1 1), This section contains troubleshooting procedures that will isolate a problem to an assembly or item that you are authorized to replace, The troubleshooting procedures are presented on easy-to-follow flowcharts that you can use without having a detailed understanding of the electrical circuits in the TD-1337(V)/G. You always start with the flowchart in paragraph 2-g. This flowchart will isolate the problem or direct you to use one of the other troubleshooting procedures in the section.
- Maintenance (page 2-3 1). Replacement procedures for the assemblies and indicators that you are authorized to replace are in this section. You will use one or more of these instructions when you are directed by troubleshooting. Installation and removal procedures for the front panel and the complete TD-1337(V)/G are also in this section.
- Storage and Shipment (page 2-52) Requirements for preparing red CESE assembly, power supply, plug-in cards, and complete TD-1337(V)/G for storage and shipment are in this section.
- Maintenance Allocation Chart (MAC) (page B-1). The MAC lists and explains the maintenance and repair functions authorized for each level of maintenance. In addition to the maintenance functions, a list of the tools and test equipment required for the functions are also in this appendix.


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Multiplexer, Digital TD-1337(V)/G.

## CHAPTER 1 INTRODUCTION

## Section 1. GENERAL INFORMATION

| Subject | Para | Page |
| :---: | :---: | :---: |
| Scope | 1-1 | 1-1 |
| Repair Parts, Special Tools, TMDE, and Support Equipment | 1-2 | -1-1 |
| Maintenance Forms, Records, and Reports . | 1-3 | 1-2 |
| Destruction of Army Materiel to Prevent Enemy Use | 1-4 | 1-2 |
| Preparation for Storage or Shipment | 1-5 | 1-2 |
| Official Nomenclature, Names, and Designations | 1-6 | 1-2 |
| Reporting Equipment Improvement Recommendations (EIR's) | 1-7 | 1-4 |
| List of Abbreviations . | 1-8 | 1-4 |

## 1-1. scope.

a. Type of ManuaL This manual contains organizational maintenance instructions for the Digital Multiplexer TD-1337(V)/G family.
b. Model Numbers and Equipment Name. Digital Multiplexer TD-1337(V)/G (hereafter referred to as the TD-1337(V)/G) is the military nomenclature assigned to a family of digital multiplexer. There are four models in the TD-1337(V)/G family. Each model is assigned its own military nomenclature as listed below.

Digital Multiplexer TD-1337(V)1/G
Digital Multiplexer TD-1337(V)2/G
Digital Multiplexer TD-1337(V)3/G
Digital Multiplexer TD-1337(V)4/G
This manual covers all four models. Differences between models are denoted throughout this manual by notes, exceptions, or other appropriate means. When the term TD-1337(V)/G is used in this manual, it means all four models,
c. Purpose of Equipment. The TD-1337(V)/G is a synchronous time division multiplexer-demultiplexer used in a satellite earth terminal. The TD-1337(V)/G provides a full duplex capability in interfacing the modem in the terminal radio equipment with ground equipments. Inputs from synchronous data users are multiplexed (combined) into a single output supergroup (SG) and supplied to the modem in the terminal radio equipment for transmission. Similarly, received $\mathrm{SG}(\mathrm{s})$ are demultiplexed (recombined) into their composite parts and supplied to the respective data users.

## 1-2. Repair Parts, Special Tools, TMDE, and Support Equipment.

a. Common Tools and Equipment. For authorized common tools and equipment, refer to the' Modified Table of Organization and Equipment (MTOE) applicable to your unit.
b. Special Tools, TMDE, and Support Equipment. No special tools, TMDE, or support equipment are required to carry out the maintenance instructions in this manual.
c. Repair Parts. Repair parts are listed and illustrated in the repair parts and special tools list (TM 11-7025-221-20P) covering organizational maintenance for this equipment.

## 1-3. Maintenance Forms, Records and Reports

a. Reports of Maintenance and Unsatisfactory Equipment. Department of the Army forms and procedures used for equipment maintenance will be those prescribed by TM 38-750, The Army Maintenance Management System (Army). Air Force personnel will use AFR 66-1 for maintenance reporting and TO-00-35D54 for unsatisfactory equipment reporting. Marine Corps personnel will use forms and procedures prescribed by TM 4700-15-1/D.
b. Report of Packaging and Handling Deficiencies Fill out and forward SF 364 (Report of Discrepancy (ROD)) as prescribed in AR 735-11-2/DLAR 4140.55 /NAVMATINST 4355.73/AFR 400-54/MCO 4430.3E.
c. Discrepancy in Shipment Report (DISREP) (SF 36 I). Fill out and forward Discrepancy in Shipment Report (DISREP) (SF 361) as prescribed in AR 55-38/NAVSUPINST 4610.33B/AFR 75-18/MCO P4610.19C/DLAR 4500.15.

## 1-4. Destruction of Army Electronics Materiel

Destruction of Army electronics materiel to prevent enemy use shall be in accordance with TM 750-244-2.

## 1-5. Preparation for Storage or Shipment.

Special instructions for preparing the TD-1337(V)/G for storage or shipment are in paragraph 2-26. Storage requirements for the TD-1337(V)/G, including administrative storage, are in aragraph 2-27. These paragraphs also contain special instructions for packaging and storing spare parts used by organizational maintenance.

## 1-6. Official Nomenclature, Names, and Designations.

Shortened nomenclature (common names) are used in this manual to make procedures easier for you to read.
a. Nomenclature Cross-Reference fist. A cross-reference between the common name and the official nomenclature for each TD-1337(V)/G model is listed below.

Nomenclature Cross-Reference List

| Common name | Official nomenclature |
| :---: | :---: |
| TD-1337(V)1/G or V1 | Multiplexer, Digital TD-1337(V)1/G |
| TD-1337(V)2/G or V2 | Multiplexer, Digital TD-1337(V)2/G |
| TD-1337(V)3/G or V3 | Multiplexer, Digital TD-1337(V)3/G |
| TD-1337(V)4/G or V4 | Multiplexer, Digital TD-1337(V)4/G |

b. Reference Designations. Each major component of the TD-1337(V)/G is assigned a reference designation. Reference designations are combinations of letters and numbers used to identify these major components. The following chart lists the reference designations applicable to the equipment covered in this manual and indicates, by a $X$, in which models each is used. The chart also lists the part No., item name, and common name for each major component. The common names are the abbreviated names used throughout this manual.

Reference Designations and Common Names

| Reference designation | Model used on |  |  |  | Part No. | Item | Common name |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | V1 | V2 | V3 | V4 |  |  |  |
| A1 | - | - | x | x | SM-D-978615 | CESE status collector card | CESE collector |
| A2 | x | x | x | x | SM-D-978560 | Synchronizer/synthesizer/ vinson buffer card | SSV |
| A3 | x | x | - | - | SM-D-978610 | TD-660 I/O card | $6601 / 0$ |
| A4 | x | x | x | x | SM-D-978590 | Loop modem/rate measurement card | Loop modem/tt meas |
| A5 | x | - | x | x | SM-D-978595 | Multiplexer input buffer card | Mux input buffer |
| A6 | x | X | $x$ | $x$ | SM-D-978570 | Multiplexer card | Mux |
| A7 | x | x | x | x | SM-D-978585 | $16 \mathrm{~Kb} / \mathrm{s}$ digital voice orderwire card | 16 DVOW |
| A8 | - | - | x | X | SM-D-978580 | $2.4 \mathrm{~Kb} / \mathrm{s}$ digital voice orderwire card | 2.4 DVOW |
| A9 | X | X | X | X | SM-D-978555 | Non-volatile memory/remote interface card | NVM |
| A10 | - | - | - | - | ---- | Spare card slot | ----- |
| A11 | X | X | - | - | SM-D-978550 | Microprocessor card (A) | M proc |
| A11 | - | - | X | X | SM-D-978630 | Microprocessor card (B) | M proc |
| A12 | x | X | X | X | SM-D-978600 | Output buffer 1 and 2 card | Output buffer 1 \& 2 |
| A13 | X | - | x | X | SM-D-978600 | Output buffer 3 and 4 card | Output buffer 3 \& 4 |
| A14 | X | - | X | - | SM-D-978600 | Output buffer 5 and 6 card | Output butier 5 \& 6 |
| A15 | X | - | X | - | SM-D-978600 | Output buffer 7 and 8 card | Output buffer 7 \& 8 |
| A16 | X | X | X | X | SM-D-978565 | Demultiplexer 1 card | Demux 1 |
| A17 | X | - | X | - | SM-D-978565 | Demultiplexer 2 card | Demux 2 |
| A18 | X | - | X | - | SM-D-978565 | Demultiplexer 3 card | Demux 3 |
| A19 | X | - | X | - | SM-D-978565 | Demultiplexer 4 card | Demux 4 |
| A20 | X | x | X | X | SM-D-978605 | Group modem card | Group modem |
| A21 | - | - | - | - | ---- | Spare card slot | ----- |
| A22 | X | x | X | X | SM-D-978575 | Phase locked loop card | PLL |
| A23 | X | X | x | X | SM-F-978490 | Multiplexer control panel assembly | Front panel |
| A23A1 | x | x | x | x | SM-D-978510 | Display card | Display |
| A23A2 | X | X | X | X | SM-D-978498 | Keyboard | Keyboard |
| A24 | X | X | X | X | SM-D-978500 | Card file assembly | Card file |
| A25 | - | - | X | x | SM-D-978520 | Red CESE assembly | Red CESE assembly |
| PS1 | X | X | X | x | SM-F-978450 | Power supply assembly | Power supply |

## 1-7. Reporting Equipment Improvement Recommendations (EIR's).

If your TD-1337(V)/G needs improvement, let us know. Send us an EIR. You, the user are the only one who can tell us what you don't like about your equipment. Let us know why you don't like the design or performance. Put it on an SF 368 (Quality Deficiency Report). Mail it to us at Commander, US Army Communications-Electronics Command and Fort Monmouth, ATTN: DRSEL-ME-MP, Fort Monmouth, New Jersey 07703 . We'll send you a reply.

## 1-8. List of Abbreviations.

Special or unusual abbreviations used in this manual and their meanings are listed below. common abbreviations that you already know are not listed.

List of Abbreviations

| Abbreviation | Meaning |
| :--- | :--- |
| ANDVT | Advanced Narrowband Digital Voice Terminal |
| ATACS | Army Tactical Area Communications System |
| b/s | Bits per second |
| CESE | Communications Equipment Support Element |
| CNCE | Communications Nodal Control Element |
| CVSD | Continuous variable slope delta |
| DLED | Digital Loop Encryption Device |
| DVOW | Digital voice orderwire |
| EMI | Electromagnetic interference |
| ESDS | Electrostatic discharge sensitive |
| FS | Frame sync |
| I/O | Input/output |
| kb/s | Kilobits per second |
| MTOE | Modified Table of Organization and Equipment |
| NRZ | Non-return to zero |
| NVM | Non-volatile memory |
| PCM | Pulse code modulation |
| PMCS | Preventive Maintenance Checks and Services |
| Rmux | Remote multiplexer |
| SG | Supergroup |
| TAMMS | The Army Maintenance Management System |
| TMDE | Test Measurement and Diagnostic Equipment |
| TRI-TAC | Joint Tactical communications |
| TSSP | Tactical Satellite Signal Processor (also means TD-1337(V)/G in |
| this manual) |  |
| TTL | Transistor-transistor-logic |
| VCXO | Voltage-controlled crystal oscillator |

## Section II. EQUIPMENT DESCRIPTION AND DATA

| Subject | Para | Page |
| :---: | :---: | :---: |
| Characteristics, Capabilities, and Features | 1-9 | 1-5 |
| Location and Description of Major Components ... | 1-10 | 1-6 |
| Identification Plates and Stencils . | 1-11 | 1-10 |
| Differences Between Models | 1-12 | 1-12 |
| Equipment Data. | 1-13 | 1-13 |

## 1-9. Characteristics, Capabilities, and Features.

## a. Characteristics.

- Interface Ground Equipments to Radio Terminal Modem. Inputs from synchronous data users are multiplexed (combined) into a single supergroup output and supplied to the modem in the terminal radio equipment for transmission. Received supergroup(s) are demultiplexed (recombined) into their composite parts and supplied to respective data users.
- Synchronous Time Division Operation. Timing between data users and TD-1337(V)/G is synchronized. Time division principles used in multiplexing and demultiplexing operations.
- Fu// Dup/ex Operation. Multiplexing and demultiplexing operations are performed independently.
b. Capabilities and Features.
- ATACS and TRI-TAC Compatible. Processes ATACS 6-bit PCM and TRI-TAC CVSD signal families.
- Operator Programmable. Operator enters configuration information by means of a front panel mounted keyboard. A 3 -line, 96 -character display presents configuration information or instructional messages to the operator.
- Non-Volatile Memory (NVM). Configuration data that has been entered is retained in NVM during electrical power interrupt and equipment turn-off periods.
- Voice Orderwires. A $16 \mathrm{~kb} / \mathrm{s}$ digital voice orderwire is selectable to secure or non-secure mode of operation. Additionally, models V3 and V4 have a separate $2.4 \mathrm{~kb} / \mathrm{s}$ digital voice orderwire capability.
- Built-in Test Circuits. Performance parameters are constantly monitored. Detected faults are displayed as discrete alarm indications or circuit card fail messages on the front panel display.
- Rack Mounted. Mounted in standard 19-inch equipment rack. Secured to rack by quick-disconnect slides and front panel fasteners.


## 1-10. Location and Description of Major Components.

Major Components Less Rear Connectors


## 1-10. Location and Description of Major Components - Continued.

Different models of the TD-1337(V)/G family are achieved by variations in plug-in card usage, presence or absence of red CESE assembly, and presence or absence of certain rear connectors. Front panel, power supply, backplane and its wiring, and case are identical for all four models.
(A) Identification Plate. Provides model of TD-1337(V)/G in use.
(B) Case. Welded enclosure that provides mounting facilities for all TD-1337(V)/G subassemblies. Openings on each side of case allow forced air from rack ducting to pass through card file area for plug-in card cooling. Openings (intake and exhaust) are covered with honeycomb electromagnetic interference (EMI) shield grilles.
(C) Front Pane/ A23. All controls and indicators used during operation and organizational maintenance are on front panel A23. A connector that interfaces the $\mathrm{H}-250$ handset is also located on the front panel. Display card A23A1 is secured to the rear surface of the front panel and includes displays that are visible through a window on the front panel. Keyboard A23A2 is located below the display window and is used to enter instructional data or cause messages to be displayed.
(D) Top Cover. Access to plug-in cards is obtained by removing top cover from case. Top cover is secured to case by turnlock fasteners that are captive to the rover. Rubber pads located on underside of the top cover press against the plug-in cards to ensure that the cards remain seated in their connectors when top cover is installed.
(E) Plug-in Cards. Plug-in cards are assigned reference designators A1 through A22. Each TD-1337(V)/G model contains a different complement of plug-in cards. The facing illustration lists and illustrates which plug-in cards are used and where they are installed in each model.
(F) Card File A24. Card file A24 is a rigid framework that houses the plug-in cards. A backplane, which is part of the card file, contains connectors into which the plug-in cards are installed. These connectors are assigned reference designators XA1 through XA22. Interconnection wiring and power distribution busses are located on bottom side of backplane. Polarizing keys are an integral part of the backplane. The plug-in cards contain cutouts which engage with polarizing keys to ensure that correct type plug-in card is installed into each backplane connector.
(G) Power Supply PS1. Power supply PS1 is mounted in the upper rear of the case. Screws captive to the power supply secure the power supply to the case. There is one connector on the bottom of the power supply that provides electrical interface with the other circuits in the TD-1337(V)/G. A guide pin located on each side of the connector ensures that the power supply connector mates properly with the case connector when installing the power supply in the case.
(H) Gaskets. Gaskets are used to provide EMI shielding. A gasket is mounted to the top cover and provides shielding for the interface between the top cover and the case. Similarity, another gasket (not shown) is mounted to the bottom cover. Gaskets are also mounted to the case and provide shielding for the front panel to case interface and the power supply to case interface. You will be requested to inspect these gaskets when performing certain maintenance procedures in this manual.

## 1-10. Location and Description of Major Components-Continued.

Rear Connectors


## 1-10. Location and Description of Major Components - Continued.

Except for the $\mathrm{H}-250$ handset connector located on front panel A23, all external connections are made to connectors located on the rear of the TD-1337(V)/G.
a. Each TD-1337(V)/G model has a different complement of rear connectors, The facing illustration shows which connectors are used on each TD-1337(V)/G model. The illustration also contains a chart that provides information about each rear connector. Using rear connector J3 as an example, the chart provides the following information:

Connector J3 is one end of cable assembly W8 (refer to b below).
Connector J3 is used on all four models.
Connector J3 provides the conditioned diphase (group modem) interface.
Input/output signals appearing at connector J3 go to or come from plug-in card A20.
When a rear connector is not used on a given model, a plate is installed to cover that connector's cutout. Organizational maintenance will be involved with these rear connectors when installing or removing a TD1337(V)/G,
b. Each rear connector, except for $\mathrm{J} 5, \mathrm{~J} 10$, and E 1 , is one end of a cable assembly. The other end of each cable assembly is one or more plugs that slip over pins on the bottom of the backplane and completes the interconnection to the plug-in card. Organizational maintenance is not authorized to remove or repair these cable assemblies (does not apply to U.S. Air Force).
c. Connector J5 is an integral part of the RFI filter which is attached to the inner rear of the case. The RFI filter provides rf filtering of the ac input power. Organizational maintenance is not authorized to replace the RFI filter (does not apply to U.S. Air Force).
d. Connector J 10 is an integral part of red CESE assembly A25. The red CESE assembly performs final formatting of CESE telemetry and outputs the data (in red) to the DLED. Red CESE assembly A25 is replaceable by organizational maintenance.
e. El is a ground stud and is used to ground the TD-1337(V)/G case.

## 1-11. Identification Plates and Stencils.



## 1-11. Identification Plates and Stencils - Continued.

Identification plates and stencils that are of importance to organizational maintenance are shown on the facing illustration.
(A) Identification Plates. Each TD-1337(V)/G has an identification plate located on the lower right front of front panel A23. The identification plate will provide you the model of the particular TD-1337(V)/G you are working with. The model No. is marked in the indicated area with a black wax pencil.
(B) Top Cover. A stencil is located in the middle of the top cover and provides the following information.

- A CAUTION that 110v ac input power exists within the TD-1337(V)/G. Additional guarding and labeling is provided within the TD-1337(V)/G to protect and inform maintenance personnel of these ac input power points.
- That the top cover must be removed when the TD-1337(V)/G is operated on a bench. This is necessary since rack ducted air is not available for plug-in card cooling.
(C) Power Supply. A stencil is located on the upper front of the power supply which advises that power must be turned off before removing power supply. POWER ON/OFF circuit breaker switch on front panel controls application of ac power to the power supply. Additionally, two CAUTION stencils (not shown) are located on the bottom (connector side) of power supply advising of high voltages within the power supply. Organizational maintenance is not authorized to remove power supply covers and gain access to internal power supply components.
(D) Case. A stencil is located on each side of the case advising that the weight of the TD-1337(V)/G (approximately 65 pounds) is such that two persons are required to lift it.
(E) Bottom Cover. A stencil is located in the middle of the bottom cover advising that 110 v ac input power exists within the TD-1337(V)/G.
(F) Front Panel. Whenever ac input power is applied to the TD-1337(V/G, it is present at terminals of the POWER ON/OFF circuit breaker switch and the POWER AC indicator. These terminals are guarded by a cover assembly to protect maintenance personnel. The rear of the cover assembly contains a CAUTION advising of the 11 O -volt power.


## 1-12. Differences Between Models.

Physical differences between models are different plug-in card usage and presence or absence of certain rear connectors. These physical differences are described in paragraph 1-10 and result in the following functional differences between models.

Functional Differences Between Models

| Capability | V1 | V2 | V3 | V4 |
| :---: | :---: | :---: | :---: | :---: |
| GROUP INTERFACES |  |  |  |  |
| Max No. of active ports (group inputs/outputs) | 8 | 2 | 8 | 4 |
| No. of unbalanced NRZ interfaces | 4 | 2 | 0 | 0 |
| No. of balanced NRZ interfaces | 8 | 2 | 8 | 4 |
| No. of conditioned diphase (group modem) interfaces | 1 | 1 | 1 | 1 |
| SG INTERFACES |  |  |  |  |
| No. SG's transmitted. | 1 | 1 | 1 | 1 |
| No. SG's received | 4 | 1 | 4 | 1 |
| ORDERWIRES |  |  |  |  |
| $16 \mathrm{~kb} / \mathrm{s}$ non-secure digital voice (H-250 handset) | yes | yes | yes | yes |
| $16 \mathrm{~kb} / \mathrm{s}$ secure digital voice (Vinson) | yes | yes | yes | yes |
| $2.4 \mathrm{~kb} / \mathrm{s}$ digital voice (ANDVT) . | no | no | yes | yes |
| MISCELLANEOUS |  |  |  |  |
| $16 / 32 \mathrm{~kb} / \mathrm{s}$ dedicated user conditioned diphase interface (loop modem) | yes | yes | yes | yes |
| CESE telemetry reporting function . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . | no | no | yes | yes |
| TD-754 demux function ..................................................................... | yes | yes | no | no |
| TD-754 mux function . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . | yes | no | no | no |
| TD-976 mode capability .................................................................. | yes | no | no | no |

## 1-13. Equipment Data.

## a. Physics/ Data.

## Dimensions:

Width (front panel) . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 19.0 inches ( 46.26 cm )
Height (front panel) . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 12.22 inches ( 31.04 cm )
Depth (including handles) . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 18.625 inches ( 47.31 cm )
Weight...................................................................................... . 62 pounds(28.1 kg)max
Cooling Air Requirements:
Source ......................................................................................................................................
Flow rate . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 50 cfm ( $1.42 \mathrm{cu} \mathrm{m} / \mathrm{min}$ )
Back pressure . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 0.5 inches ( 1.27 cm ) max
Temperature . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 145 ${ }^{\circ} \mathrm{F}$ ( $62.78^{\circ} \mathrm{C}$ ) max
Power:
Supply voltage . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 115v ( 103.5 to 126.5v), 45 to 440 Hz
Consumption .......................................................................................... . 140 watts max
Overload protection . . . . . . . . . . . . . . . . . . . AC POWER ON/OFF circuit breaker switch on front panel
b. Satellite Side (Supergroup) Interfaces.

| Format | Unbalanced NRZ |
| :---: | :---: |
| Rates | $16 \mathrm{~kb} / \mathrm{s}$ to $4664 \mathrm{~kb} / \mathrm{s}$ in $8 \mathrm{~kb} / \mathrm{s}$ increments or $4915.2 \mathrm{~kb} / \mathrm{s}$ |
| Data 1 | . . . 0.0 to -0.4v |
| Data O | 2.2 to -2.6v |
| Input/output impedance | . 910 ohms |

c. Earth Side Interfaces.

Unbalanced NRZ Group (V1and V2 models only):
Format . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . Unbalanced NRZ
Rates . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 288 and 576 kb/s (input) 288, 576, and $1152 \mathrm{~kb} / \mathrm{s}$ (output)
Data 1 .........................................................................................................0.0 to -0.4v
Data 0 . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . .2.2 to -2.6v
input/output impedance . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 91 ohms
Balanced NRZ Group:
Format . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . Balanced NRZ (two wire system)
 and $1152 \mathrm{~kb} / \mathrm{s} .4915 .2 \mathrm{~kb} / \mathrm{s}$ for TD-976.mode.
Data 1 High side of two wire system positive with respect to low side.
Data O . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . High side of two wire system negative with respect to low side.
Transmit level . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 87mv to 3 v

Input/output impedance ............................................................................................................ 100 ohms

## 1-13. Equipment Data - Continued.

Group Modem:
Group Data:
Format Conditioned diphase
Rates .72. $128,144,256,288,512,576,1024$, and $1152 \mathrm{~kb} / \mathrm{s}$
Data . Intelligence contained in signal transitionsrather than voltage levels.
Transmit level 3.0 v (2.4 to 3.6v) peak-to-peak
Receive level Transmit level fixed; receive levelis that received through appropriate length ofCX-11230/G cable.
Cable length 0 to 2 miles for data rates of 72 to $576 \mathrm{~kb} / \mathrm{s}$.0 to 1 mile for data rates of 1024 and $1152 \mathrm{~kb} / \mathrm{s}$.Internal cable equalization circuits compensate receivesignal based on cable length in $1 / 4$-mile increments.
Input/output impedance
58 ohms
Combined Digital Orderwire:
AvailabilityTransmitted along with group data when groupdata rates are $256 \mathrm{~kb} / \mathrm{s}$ and above.
Format ..... NRZ
Rates:
CESE data (V3 and V4 models only) ..... $2 \mathrm{~kb} / \mathrm{s}$
Digital voice orderwire ..... 16 kb/s
Data 1 ..... $+0.5 \mathrm{v}(+0.45$ to $+0.55 \mathrm{v})$
Data 0 ..... $4.5 \mathrm{v}(-0.45$ to $-0.55 \mathrm{v})$
Dedicated User (Loop Modem):
Format Conditioned diphase
Rates ..... 16 or $32 \mathrm{~kb} / \mathrm{s}$
Data Intelligence contained in signal transitionsrather than voltage levels.
Transmit level 3.0 v (2.7 to 3.3v) peak-to-peakReceiver sensitivity100mv peak-to-peak
Input/output impedance ..... 125 ohms
16 kb/s Digital Voice Orderwires:
Non-Secure Mode:
Interface device ..... H-250 Handset
Format ..... Analog
Secure Mode:
Interface device ..... W. $57 / 58$ Vinson
Format ..... Digial $\pm 6 \mathrm{v}$
Rate ..... $16 \mathrm{~kb} / \mathrm{s}$
$2.4 \mathrm{~kb} / \mathrm{s}$ Digital Voice Orderwire (V3 and V4 models only): Interface device Advanced narrowband digital voice terminal
Format Digital, $\pm 6 \mathrm{v}$
Rate ..... $2.4 \mathrm{~kb} / \mathrm{s}$

## 1-13. Equipment Data-Continued.

```
CESE Functions (V3 and V4 models only):
    Status Point Inputs:
```



```
    Normal condition (any point) . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . to to +5.0v
    Fault condition (any point) . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 0.0 to +0.4V
    Data to DLED (Red):
    Format . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . .Digital, m6v
    Rate . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . }150\mathrm{ b/s
    Data from DLED (Black):
```



```
    Rate . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . .................................2kb/
    CESE Telemetry Outputs:
```



```
    Format . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . Balanced NRZ
    Rate.........................................................................................................................
```

            Section III. PRINCIPLES OF OPERATION
    | Subject | Para | Page |
| :---: | :---: | :---: |
| Multiplexer Section Block Diagram Discussion (V1/V2 Models) | 1-14 | 1-16 |
| Demultiplexer Section Block Diagram Discussion (V1/V2 Models) | 1-15 | 1-18 |
| Multiplexer Section Block Diagram Discussion (V3/V4 Models) | 1-16 | 1-20 |
| Demultiplexer Section Block Diagram Discussion (V3/V4 Models) | 17 | 1-22 |

## OVERVIEW

This section contains card level block diagram discussions. Separate discussions are provided for the multiplexer and demultiplexer sections of V1/V2 models and V3/V4 models. These discussions describe the major data paths and can be of assistance during troubleshooting operations.

## 1-14. Multiplexer Section Block Diagram Discussion (V1/V2 Models).


(A) M proc card A11 contains the microprocessor and controls TD-1337(V)/G operation. Data are transferred between the microprocessor and other cards over an 8-bit bidirectional data bus.
(B) Front panel A23 provides for operator interface. Display card A23A1 provides the operator with information via a 3-line display and five alarm indicators. Keyboard A23A2 is used to enter instructional data or cause messages to be displayed.
(C) NVM card A9 contains non-volatile memory (NVM) circuits that retain configuration data entered by the operator. Up to two operating configurations can be entered and retained. A battery, on the card, provides power to the memory circuits when the TD-1337(V)/G is turned off or input ac power is lost.
A remote interface function provides for sending (or receiving) configuration data in NVM to (or from) a standby TD-1337(V)/G.

An address decoding function decodes addresses from M proc card A11 to generate I/O read/write strobes. These strobes allow the microprocessor to communicate (write and read data) with other cards over the 8 -bit data bus.
(D) The synthesizer circuit on SSV card A2 produces a mux clock output. The rate of the mux clock is dependent on system operating configuration and will be between 16 kHz and 4664 kHz in 8 kHz steps. Rate of SG output is equal to rate of the mux clock.

## 1-14. Multiplexer Section Block Diagram Discussion (V1/V2 Models) - Continued.

(E) The rate measurement circuit on loop modem/rt mess card A4 measures the frequency of selected timing signals within the TD-1337(V)/G. The frequency of each selected timing signal is counted and compared by the microprocessor to a stored value. Any errors in this measurement result in alarm displays.
(F) Input data from up to four TD-660/G multiplexer (in unbalanced NRZ format) are processed by receivers on 660 I/O card A3. Data are converted to a NRZ transistor-transistor logic (TTL) format (logic 1 is +5 volts and logic O is O volts). Timing is recovered based on data transitions. Data and timing for each group input are applied to their respective input buffer.
(G) The receiver on group modem card A20 processes the group modem conditioned diphase input. A combined digital orderwire may also be received on this input. The group data and orderwire inputs are separated and converted into TTL formats. Timing is recovered from the data. Group data and timing are applied to the respective input buffer. Orderwire data are routed to 16 DVOW card A7.
(H) There are eight input buffers; one for each potential input port. Buffers for groups 1 and 2 are located on mux card A6. Buffers for groups 3 thru 8 are on mux input buffer card A5. Each buffer provides an elastic storage function for one group input. Data for each group are clocked into its buffer at its incoming data rate. Data are strobed out of the buffers and onto the mux transmit data bus in response to mux strobes. Thus, data are clocked into each buffer at a regular rate and strobed out when it is to be inserted into the SG,
(1) Incoming $16 \mathrm{~kb} / \mathrm{s}$ orderwire data from the KY-57/58 Vinson are processed by the Vinson buffer on SSV card A2 for application to 16 DVOW card A7. Processing entails converting the data to a TTL format and buffering. The KY-57/58 Vinson is not synchronized to the TD-1337(V)/G. Therefore, buffering is required to accommodate for differences between the clock source in the KY-57/58 Vinson and TD-1337(V)/G timing.
(J) 16 DVOW card A7 provides access to the mux transmit data bus for the $16 \mathrm{~kb} / \mathrm{s}$ orderwires. The three $16 \mathrm{~kb} / \mathrm{s}$ orderwires are: the Vinson orderwire input from SSV card A2, the CNCE orderwire input from group modem card A20, and the $\mathrm{H}-250$ handset input. Only one input can be accepted at a time, and entry is on a first-come, first-served basis. The $\mathrm{H}-250$ handset input is in analog form and is converted to a TTL format by 16 DVOW card A7. Data for a given orderwire are processed and entered into a buffer. Data are strobed out and onto the mux transmit data bus in response to mux strobes. Ring codes to be transmitted are received from the microprocessor and strobed onto the mux transmit data bus.
(K) The loop modem receiver on loop modem/rt mess card A4 processes the incoming $16 \mathrm{~kb} / \mathrm{s}$ or $32 \mathrm{~kb} / \mathrm{s}$ conditioned diphase dedicated user input. The input is converted to a TTL format and entered into a buffer. Data are strobed out and onto the mux transmit data bus in response to mux strobes.
(L) The mux circuits on mux card A6 generate mux strobes that control strobing of data onto the mux transmit data bus. In this way, all parts of the SG are assembled in the proper sequence and at the proper time. Data on the mux transmit data bus are converted to an unbalanced NRZ format and applied to the modem.
(M) PLL card A22 produces the major timing signals used to control TD-1337(V)/G operation. These timing signals are derived from a voltage-controlled crystal oscillator (VCXO) on the card. Method of VCXO control is based on the timing source selection made during configuration. If CNCE or external standard selection is made, the VCXO is controlled by a phase-locked loop that receives timing from one of the group inputs, If master is selected, the VCXO is driven to its nominal mid-range by the microprocessor, If slave is selected, the VCXO is controlled by the microprocessor in response to control telemetry data received in an incoming SG.

## 1-15. Demultiplexer Section Block Diagram Discussion (V1/V2 Models).



A frame sync detector circuit on SSV card A2 is time shared by each active demux card. This circuit sequentially monitors each incoming $S G$ for a 20-bit sync word. When the sync word is found, a frame sync (FS) signal is applied to the demux card supplying the SG. This allows the demux card to start operating at the proper time. Thereafter, each demux card performs a sync maintenance function to ensure that it is still in sync. If sync is lost, the demux card is turned off and the frame sync detector would again attempt to acquire sync.

## 1-15. Demultiplexer Section Block Diagram Discussion (V1/V2 Models) - Continued.

(B) Each demux card contains a group strobe generator which is turned on by a FS signal. This synchronizes the group strobe generator with the incoming SG. The group strobe generator produces a demux strobe for each of the various component parts of the incoming SG. By routing a SG and a specific demux strobe to another circuit, that circuit will use the strobe to extract (demultiplex) designated data out of the incoming serial SG data stream. SG and strobe routing to output buffer cards are controlled by the demux cards in response to configuration data in NVM. Thus, for example, a SG and a demux strobe for specific group data in that SG are routed from a demux card to a particular output buffer input. This enables that output buffer to extract designated group data out of a specific SG.
(C) Output buffer cards A12 through Al 5 provide elastic storage for demultiplexed group data. Each card contains two output buffers. Buffer length is varied dependent on group data rate under microprocessor control. For group data rates of $1024 \mathrm{~kb} / \mathrm{s}$ and $1152 \mathrm{~kb} / \mathrm{s}$, an odd numbered buffer is strapped to its associated even numbered buffer to make one large buffer.

Data are strobed into a buffer by the applied demux strobe. Since the demux strobe is synchronized to the incoming SG, it contains variations due to satellite path delays. Also, data bits for a given group are not regularly spaced in the SG. Thus, data are strobed into a buffer at an irregular rate. Data are clocked out of a buffer by a synchronous buffer output clock timing signal from PLL card A22.

The output of each buffer is routed through a driver and available in a balanced NRZ format. Outputs are also available in a TTL format for use by other cards.
(D) Outputs from buffers 1 through 4 are routed to $660 \mathrm{l} / \mathrm{O}$ card A3. Drivers on this card convert the data to an unbalanced NRZ format. If the TD-754 demux option has been selecied, a 1152 $\mathrm{kb} / \mathrm{s}$ output from buffer 1 and/or buffer 3 will be outputted in parallel, in unbalanced NRZ format, at ports 1 and 2 or 3 and 4 .
(E) 660 I/O card A3 also contains circuits to accomplish a multiplexing function normally performed by a TD-754/G (TD-754 mux option), If this option is selected, the data outputs of buffers 5 and 6 (each at $576 \mathrm{kbs} /$ ) are combined by card A3 into a $1152 \mathrm{~kb} / \mathrm{s}$ signal, routed through the driver associated with buffer 5, and made available at port 5 in a balanced NRZ format. Similarly, the outputs of buffers 7 and 8 can be combined and made available at port 7 in a balanced NRZ format.
(F) Group data outputs from buffers 1, 3, and 5 are applied to group modem card A20. Also, a 16 $\mathrm{kb} / \mathrm{s}$ orderwire input is received from 16 DVOW card A7. Based on configuration data in NVM, one of the group data inputs is selected. The orderwire input is also selected if the group data rate is $256 \mathrm{~kb} / \mathrm{s}$ or higher. The selected group data input is converted to a conditioned diphase format and combined with the orderwire, if present, for transmission to the CNCE.
(G) 16 DVOW card A7 receives a SG and associated demux strobe from each active demux card. These inputs are handled on a first-come, first-sewed basis. A ring detector will detect when an incoming call is for your station. Orderwire data is extracted out of the SG and buffered. Orderwire data are routed to group modem card A20 and the Vinson driver on SSV card A2 if the call is secure. Orderwire data for non-secure calls are routed to the $\mathrm{H}-250$ handset.
(H) The Vinson driver on SSV card A2 converts orderwire data received from 16 DVOW card A7 to a MIL-STD-188-100 format as required by the Vinson.
(1) The loop modem driver on loop modem/rt mess card A4 receives a SG and associated demux strobe from each active demux card, Based on configuration data in NVM, one SG input will be selected for processing. Dedicated user data is extracted from the selected SG, buffered, and converted to a conditioned diphase format for output to the dedicated user.

## 1-16. Multiplexer Section Block Diagram Discussion (V3/V4 Models).


(A) M proc card A11 contains the microprocessor and controls TD-1337(V)/8 operation. Data are transferred between the microprocessor and other cards over an 8-bit hi-directional data bus.
(B) Front panel A23 provides for operator interface. Display card A23A1 provides the operator with information via a 3-line display and five alarm indicators. Keyboard A23A2 is used to enter instructional data or cause messages to be displayed.
(C) NVM card A9 contains non-volatile memory (NVM) circuits that retain configuration data entered by the operator. Up to two operating configurations can be entered and retained. A battery, on the card, provides power to the memory circuits when the TD-1337(V)/G is turned off or input ac power is lost.
A remote interface function provides for sending (or receiving) configuration data in NVM to (or from) a standby TD-1337(V)/G.
An address decoding function decodes addresses from M proc card A11 to generate I/O read/write strobes. These strobes allow the microprocessor to communicate (write and read data) with other cards over the 8 -bit data bus.
(D) The synthesizer circuit on SSV card A2 produces a mux clock output. The rate of the mux clock is dependent on system operating configuration and will be between 16 kHz and 4664 kHz in 8 kHz steps. Rate of SG output is equal to rate of the mux clock.
(E) The rate measurement circuit on loop modem/rt mess card A4 measures the frequency of selected timing signals within the TD-1337(V)/G. The frequency of each selected timing signal is counted

## 1-16. Multiplexer Section Block Diagram Discussion (V3/V4 Models) - Continued.

and compared by the microprocessor to a stored value. Any errors in this measurement result in alarm displays.
(F) The receiver on group modem card A20 processes the group modem conditioned diphase input. A combined digital orderwire may also be received on this input. The group data and orderwire inputs are separated and converted into TTL formats. Timing is recovered from the data. Group data and timing are applied to the respective input buffer. Orderwire data are routed to 16 DVOW card A7.
(G) There are eight input buffers; one for each potential input port. Buffers for groups 1 and 2 are located on mux card A6, Buffers for groups 3 through 8 are on mux input buffer card A5. Each buffer provides an elastic storage function for one group input. Data for each group are clocked into its buffer at its incoming data rate. Data are strobed out of the buffers and onto the mux transmit data bus in response to mux strobes. Thus, data are clocked into each buffer at a regular rate and strobed out when it is to be inserted into the SG.
(H) Incoming $16 \mathrm{~kb} / \mathrm{s}$ orderwire data from the KY-57/58 Vinson are processed by the Vinson buffer on SSV card A2 for application to 16 DVOW card A7. Processing entails converting the data to a TTL format and buffeting. The KY-57/58 Vinson is not synchronized to the TD-1337(V)/G. Therefore, buffering is required to accommodate for differences between the clock source in the KY-57/58 Vinson and TD-1337(V)/G timing.
(1) 16 DVOW card A7 provides access to the mux transmit data bus for the $16 \mathrm{~kb} / \mathrm{s}$ orderwires. The three $16 \mathrm{~kb} / \mathrm{s}$ orderwires are: the Vinson orderwire input from SSV card A2, the CNCE orderwire input from group modem card A20, and the $\mathrm{H}-250$ handset input. Only one input can be accepted at a time, and entry is on a first-come, first-sewed basis. The H-250 handset input is in analog form and is converted to a TTL format by 16 DVOW card A7, Data for a given orderwire are processed and entered into a buffer. Data are strobed out and onto the mux transmit data bus in response to mux strobes. Ring codes to be transmitted are received from the microprocessor and strobed onto the mux transmit data bus.
J Orderwire transmit circuits on 2.4 DVOW card A8 provide access to the mux transmit data bus for the $2.4 \mathrm{~kb} / \mathrm{s}$ ANDVT input. The input is converted to a TTL format and entered into a buffer. In turn, data are strobed out and onto the mux transmit data bus in response to mux strobes. Ring codes to be transmitted are received from 16 DVOW card A7 and strobed onto the mux transmit data bus.
(K) The loop modem receiver on loop modem/rt mess card A4 processes the incoming $16 \mathrm{~kb} / \mathrm{s}$ or $32 \mathrm{~kb} / \mathrm{s}$ conditioned diphase dedicated user input. The input is converted to a TTL format and entered into a buffer. Data are strobed out and onto the mux transmit data bus in response to mux strobes.
(L) Under microprocessor control, CESE collector card AI monitors up to 56 external status points. The status points are scanned and a message is assembled that is applied to red CESE assembly A25 which converts the message to a $150 \mathrm{~b} / \mathrm{s}$ serial data stream for application to an external DLED. The DLED encrypts the message and applies it back to card AI as a $2 \mathrm{~kb} / \mathrm{s}$ serial data stream. The input from the DLED is converted to a TTL format and entered into a buffer. Data are strobed out and onto the mux transmit data bus in response to mux strobes.
The mux circuits on mux card A6 generate mux strobes that control strobing of data onto the mux transmit data bus. In this way, all parts of the SG are assembled in the proper sequence and at the proper time. Data on the mux transmit data bus are converted to an unbalanced NRZ format and applied to the modem.
(N) PLL card A22 produces the major timing signals used to control TD-1337(V)/G operation. These timing signals are derived from a voltage-controlled crystal oscillator (VCXO) on the card, Method of VCXO control is based on the timing source selection made during configuration. If CNCE or external standard selection is made, the VCXO is controlled by a phase-locked loop that receives timing from one of the group inputs. If master is selected, the VCXO is driven to its nominal mid-range by the microprocessor. If slave is selected, the VCXO is controlled by the microprocessor in response to control telemetry data received in an incoming SG.

## 1-17. Demultiplexer Section Block Diagram Discussion (V3/V4 Models).



## 1-17. Demultiplexer Section Block Diagram Discussion (V3/V4 Models) - Continued.

(B)

Each demux card contains a group strobe generator which is turned on by a FS signal. This synchronizes the group strobe generator with the incoming SG. The group strobe generator produces a demux strobe for each of the various component parts of the incoming SG. By routing a SG and a specific demux strobe to another circuit, that circuit will use the strobe to extract (demultiplex) designated data out of the incoming serial SG data stream. SG and strobe routing to output buffer cards are controlled by the demux cards in response to configuration data in NVM. Thus, for example, a SG and a demux strobe for specific group data in that SG are routed from a demux card to a particular output buffer input. This enables that output buffer to extract designated group data out of a specific SG.
(C) Output buffer cards Al 2 through AI 5 provide elastic storage for demultiplexed group data. Each card contains two output buffers. Buffer length is varied dependent on group data rate under microprocessor control. For group data rates of $1024 \mathrm{~kb} / \mathrm{s}$ and $1152 \mathrm{~kb} / \mathrm{s}$, an odd numbered buffer is strapped to its associated even numbered buffer to make one large buffer.
Data are strobed into a buffer by the applied demux strobe. Since the demux strobe is synchronized to the incoming SG, it contains variations due to satellite path delays. Also, data bits for a given group are not regularly spaced in the SG. Thus, data are strobed into a buffer at an irregular rate. Data are clocked out of a buffer by a synchronous buffer output clock timing signal from PLL card A22.
The output of each buffer is routed through a driver and available in a balanced NRZ format. Outputs are also available in a TTL format for use by other cards.
(D) Group data outputs from buffers 1, 3, and 5 are applied to group modem card A20. Based on configuration data in NVM, one of the group data inputs is selected for processing.
A $16 \mathrm{~kb} / \mathrm{s}$ orderwire input and CESE data inputs are also received. CESE data inputs consist of local CESE data from CESE collector card A1 in the multiplexer section and CESE data received through demux 1. Configuration data in NVM will determine which CESE data input is selected for processing. If the group data rate is $256 \mathrm{~kb} / \mathrm{s}$ or higher, the $16 \mathrm{~kb} / \mathrm{s}$ orderwire and the selected CESE data input are combined into a digital data orderwire.
The selected group data input is converted to a conditioned diphase format and combined with the digital data orderwire, if present, for transmission to the CNCE.
(E) 16 DVOW card A7 receives a SG and associated demux strobe from each active demux card. These inputs are handled on a first-come, first-sewed basis. A ring detector will detect when an incoming call is for your station. Orderwire data is extracted out of the SG and buffered. Orderwire data are routed to group modem card A2O and the Vinson driver on SSV card A2 if the call is secure. Orderwire data for non-secure calls are routed to the $\mathrm{H}-250$ handset.
(F) The Vinson driver on SSV card A2 converts orderwire data received from 16 DVOW card A7 to a MIL-STD-188-100 format as required by the Vinson.
(G) Orderwire receive circuits on 2.4 DVOW card A8 receive a SG and associated demux strobe from each active demux card. These inputs are handled on a first-come, first-sewed basis. $2.4 \mathrm{~kb} / \mathrm{s}$ orderwire data is extracted out of the SG, buffered, and converted to a MIL-STD-188-100 format as required by the ANDVT.
(H) The loop modem driver on loop modem/rt mess card A4 receives a SG and associated demux strobe from each active demux card. Based on configuration data in NVM, one SG input will be selected for processing. Dedicated user data is extracted from the selected SG, buffered, and converted to a conditioned diphase format for output to the dedicated user.
(1) There are four CESE buffers on 2.4 DVOW card A8. Each buffer extracts CESE data out of a received SG, buffers the data, and outputs it in a balanced NRZ format.

## CHAPTER 2 <br> MAINTENANCE INSTRUCTIONS

## Section I. SERVICE UPON RECEIPT

| subject | Para | Page |
| :---: | :---: | :---: |
| Site and Shelter Requirements | 2-1] | 2-1 |
| Power Requirements | 2-2 | 2-1 |
| Rack Mounting Requirements | 2-3 | 2-1 |
| Interface Connector Data | 2-4 | 2-2 |
| Rear Connector Signal-To-Pin Relationships. | 2-5 | 2-3 |
| Unpacking | 2-6] | 2-8 |
| Checking Unpacked Equipment | 2-7 | 2-9 |
| Installation Instructions | 2-8 | 2-10 |

## OVERVIEW

This section provides service upon receipt instructions.
. Normally, you will receive your TD-1337(V)/G already installed in a rack with proper cabling connected. However, if you have to plan a TD-1337(V)/G installation, refer to paragraphs 2-2 through 2-5 which contain physical and electrical interface requirements.
. Unpacking instructions are contained in paragraphs 2-6 and 2-7.
. Refer to paragraph 2-16 for procedures to install a TD-1337(V)/G.

## 2-1. Site and Shelter Requirements.

The TD-1337(V)/G is designed to be installed in an equipment rack and operated in the environment of a shelter or a fixed plant. Normally, you will receive your TD-1337(V)/G already installed in a rack with proper cabling connected. In this case, appropriate physical and electrical interface requirements were considered and accounted for during design of the rack. Use the information in paragraphs 2-2 through 2-5 if you have to plan a TD-1337(V)/G installation.

## 2-2. Power Requirements.

The TD-1337(V)/G requires an external power input of 115 v ( 103.5 to 126.5 v ), 45 to $440 \mathrm{~Hz}, 140$ watts maximum.

## 2-3. Rack Mounting Requirments.

The TD-1337(V)/G is built for mounting in a 19 -inch equipment rack. The following conditions must be considered in the installation planning.
a. Mounting S/ides. The TD-1337(V)/G is slide mounted in an equipment rack. One set of inner-channel slides and one set of matching outer-channel slides are required to support the TD-1337(V)/G in a rack. The inner-channel slides SM-D-777131-6 (right) and SM-D-777132-6 (left) come installed on a TD-1337(V)/G. The outer-channel slides SM-D-777131-5 (right) and SM-D-777132-5 (left) are not supplied with a TD1337(V)/G. These slides must be obtained and mounted in the rack.
b. Rack Cooling System. The rack cooling system must be capable of supplying at least 50 cfm ( $1.42 \mathrm{cu} \mathrm{m} / \mathrm{min}$ ) of air flow for cooling the TD-1337(V)/G. This air is directed into the side panel air inlet and over the power supply. The temperature of the cooling air must not exceed $145^{\circ} \mathrm{F}\left(62.8^{\circ} \mathrm{C}\right)$.

## 2-3. Rack Mounting Requirements - Continued.

c. Space Requirements. Approximately 24 inches of clearance is required directly in front of the rack. When the TD-1337 (V)/G is pulled out on the slides, there must be sufficient clearance to service the sides, top, bottom, and rear of the unit. The rack must contain adequate space to make the necessary cable connections, with service loops, to the rear of the TD-1337(V)/G.
d. Location in Rack. When mounting the TD-1337(V)/G in a rack, choose a location in the rack that is not at the extreme bottom or top of the rack. Operator actions are accomplished at the keyboard and display located on the front of the TD-1337(V)/G. Organizational maintenance tasks will require access to the top of the TD-1337(V)/G when it is pulled out on the slides.

## 2-4. Interface Connector Data.

All external connections are made to connectors J 1 through J 12 located cm the rear of the TD-1337(V)/G. As explained in paragraph 1-10 each TD-1337(V)/G model has a different complement of rear connectors. The following chart provides data as to what type connector will mate with each TD-1337(V)/G rear connector. Paragraph 2-5 lists the signals for each pin of each rear connector.

## TD-1337(V)/G Connector Data

| TD-1337(V)/G connector |  | Mating connector type | Function |
| :---: | :---: | :---: | :---: |
| No. | Type |  |  |
| J1 | MS27656T23B21P | MS27467T23B21S | Supergroups |
| J2 | MS27656T13B35PA | MS27467T13B35SA | Remote interface |
| J3 | MS27656T17B8P | MS27467T17B8S | Conditioned diphase (group modem) |
| J4 | MS27656T17B35PA | MS27467T17B35SA | CESE telemetry, 2.4 DVOW, and DLED interface (black) (V3 and V4 models only) |
| J5 | MS3114E-12-3P | MS3116E-12-3S | Ac power input |
| J6 | MS27656T17B35P | MS27467T17B35S | Balanced NRZ groups 1 thru 4 |
| J7 | MS27656T17B35P | MS27467T17B35S | Balanced NRZ groups 5 thru 8 (V1 and V3 models only) |
| J8 | MS27656T21B35P | MS27467T21B35S | CESE status point inputs (V3 and V4 models only) |
| J9 | MS27656T21B16P | MS27467T21B16S | Unbalanced NRZ (TD-660) groups 1 and 2 (V1 and V2 models only) |
| J10 | MS27656T9B35P | MS27467T9B35S | DLED interface (red) (V3 and V4 models only) |
| $J 11$ | MS27656T21B16P | MS27467T21B16S | Unbalanced NRZ (TD-660) groups 3 and 4 (V1 model only) |
| J12 | MS27656T13B35P | MS27467T13635S | Vinson interface, $16 / 32 \mathrm{~kb} / \mathrm{s}$ dedicated user, and remote alarms |

## 2-5. Rear Connector Signal-To-Pin Relationships.

Each of the 12 rear connectors are shown below. Adjacent to each connector is a chart listing the signal on each connector pin. The "l/O" column of each chart identifies whether the signal is an input (I) or output (0) signal.
a. Connector J1. Supergroups enter and exit the TD-1337(V)/G through this connector.

b. Connector J2. Remote interface signals to/from a standbyTD-1337(V)/G use this connector.

| J2 |  | Signal-To-Pin Relationship |
| :---: | :---: | :---: |
| Pin | 1/0 | Signal |
| 1 | 0 | NVM 5v supply |
| 2 | 1 | NVM 5v load |
| 3-14 | -- | Not used |
| 15 | 0 | Transmitter data |
| 16 | 1 | Receiver data |
| 17 | 0 | Data terminal ready |
| 18 | 1 | Data set ready |
| 19 | 0 | Request to send |
| 20 | 1 | Clear to send |
| 21 | -- | Ground |
| 22 | -- | Ground |



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## 2-5. Rear Connector Signal-To-Pin Relationships - Continued.

c. Connector J3. Conditioned diphase signals to/from a CNCE (group modem) use this connector.


J3 Signal-To-PIn Relationship

| Pin | I/O | Signal |
| :---: | :---: | :---: |
| A | I | Conditioned diphase modem receive <br> data |
| B | I | Conditioned diphase modem receive <br> data shield |
| C,D | -- | Not used <br> Eonditioned diphase modem transmit <br> data <br> Eonditioned diphase modem transmit |
| F | 0 | data shield |
| G,H | -- | Not used |$\quad$| Not |
| :--- |

d. Connector J4 (V3 and V4 models only). This connector is used for CESE telemetry output signals, input/output signals for $2.4 \mathrm{~kb} / \mathrm{s}$ ANDVT, and input signals from the DLED.


## 2-5. Rear Connector Signal-To-Pin Relationships - Continued.

e. Connector J5. Input ac power is routed through this connector.


J5 Signal-To-Pin Relationship

| Pin | I/O | Signal |
| :--- | :--- | :--- |
| A | I | 115 v ac |
| B | I | Ground |
| C | I | Neutral |

f. Connectors J6 (all models) and J7 (V1 and V3 models on/y). These connectors are used for balanced NRZ inputs/outputs. Connector J6 is for groups 1 through 4 and connector J7 is for groups 5 through 8.


## 2-5. Rear Connector Signal-To-Pin Relationships - Continued.

| J7 Signal-To-Pin Relationship |  |  |
| :---: | :--- | :--- |
| Pin | I/O | Signal |
| 1 | I | Receive timing group 5 low side |
| 2 | I | Receive timing group 5 high side |
| 3 | -- | Not used |
| 4 | O | Transmit timing buffer 5 low side |
| 5 | O | Transmit timing buffer 5 high side |
| 6 | I | Receive timing group 5 shield |
| 7 | I | Receive data group 6 shield |
| 8 | I | Receive timing group 6 low side |
| 9 | I | Receive timing group 6 high side |
| 10 | O | Transmit data buffer 5 shield |
| 11 | O | Transmit timing buffer 5 shield |
| 12 | I | Receive data group 5 shield |
| 13 | I | Receive data group 6 low side |
| 14 | I | Receive data group 6 high side |
| 15 |  | Receive timing group 6 shield |
| 16 | O | Transmit timing buffer 6 shield |
| 17 | O | Transmit data buffer 5 low side |
| 18 | O | Transmit data buffer 5 high side |
| 19 | I | Receive data group 5 low side |
| 20 | I | Receive data group 5 high side |
| 21 | O | Transmit data buffer 6 low side |
| 22 | O | Transmit data buffer 6 high side |
| 23 | O | Transmit timing buffer 6 low side |
| 24 | O | Transmit timing buffer 6 high side |
| 25,26 | -- | Not used |
| 27 | O | Transmit data buffer 7 shield |
| 28 | -- | Not used |

J7 Signal-To-Pin Relationship - Continued

| Pin | I/O | Signal |
| :---: | :---: | :--- |
| 29 | O | Transmit data buffer 6 shield |
| 30,31 | -- | Not used |
| 32 | O | Transmit timing buffer 7 low side |
| 33 | O | Transmit timing buffer 7 high side |
| 34 | O | Transmit data buffer 7 low side |
| 35 | O | Transmit data buffer 7 high side |
| 36 | I | Receive data group 8 low side |
| 37 | I | Receive data group 8 high side |
| 38 | O | Transmit data buffer 8 low side |
| 39 | O | Transmit data buffer 8 high side |
| 40 | O | Transmit timing buffer 7 shield |
| 41 | I | Receive timing group 7 shield |
| 42 | I | Receive data group 7 low side |
| 43 | I | Receive data group 7 high side |
| 44 | I | Receive data group 8 shield |
| 45 | O | Transmit timing buffer 8 shield |
| 46 | O | Transmit data buffer 8 shield |
| 47 | i | Receive timing group 7 low side |
| 48 | I | Receive timing group 7 high side |
| 49 | I | Receive data group 7 shield |
| 50 | I | Receive timing group 8 shield |
| 51 | O | Transmit timing buffer 8 low side |
| 52 | O | Transmit timing buffer 8 high side |
| 53 | -- | Not used |
| 54 | I | Receive timing group 8 low side |
| 55 | I | Receive timing group 8 high side |

g. Connector J8 (V3 and V4 models only). CESE status point inputs are routed through connector J8. There is a CESE message that will be displayed as part of the alarms recall routine (see TM 11-7025-221-10) when a CESE status point input reports a failure condition. The failure message associated with each status point input is shown in parenthesis. For example, "945TX1" is the message that would be displayed if status point 1 reports a failure. Status points 51 through 56 are spares and have no message assignments.


| J8 Signal-To-Pin Relationship |  |  |
| :---: | :---: | :--- |
| Pin | I/O | Signal |
| 1 | I | Status point 1 (945TX1) |
| 2 | I | Status point 2 (945RX1) |
| 3 | I | Status point 3 (945TX2) |
| 4 | I | Status point 4 (945RX2) |
| 5 | I | Status point 5 (945TX3) |
| 6 | I | Status point 6 (945RX3) |
| 7 | I | Status point 7 (945TX4) |
| 8 | i | Status point 8 (945RX4) |
| 9 | I Status point 9 | (945TX5) |

## 2-5. Rear Connector Signal-T\&Pin Relationships - Continued.

| Pin | I/O | Signal |
| :---: | :---: | :---: |
| 10 | I | Status point 10 (945RX5) |
| 11 | 1 | Status point 11 (AJ1TX) |
| 12 | 1 | Status point 12 (AJ1RX1) |
| 13 | I | Status point 3 (AJ1RX2) |
| 14 | I | Status point 4 (AJ1RX3) |
| 15 | 1 | Status point 5 (AJ1RX4) |
| 16 | 1 | Status point 6 (AJ2TX) |
| 17 | , | Status point 7 (AJ2RX1) |
| 18 | I | Status point 8 (AJ2RX2) |
| 19 | 1 | Status point 9 (AJ2RX3) |
| 20 | 1 | Status point 20 (AJ2RX4) |
| 21 | 1 | Status point 21 (DCSCU1) |
| 22 | 1 | Status point 22 (DCSCU2) |
| 23 | 1 | Status point 23 (HPA1) |
| 24 | 1 | Status point 24 (HPA2) |
| 25 | , | Status point 25 (DLED) |
| 26 | 1 | Status point 26 (TED1) |
| 27 | 1 | Status point 27 (TED2) |
| 28 | 1 | Status point 28 (TED3) |
| 29 | 1 | Status point 29 (TED4) |
| 30 | 1 | Status point 30 (TED5) |
| 31 | 1 | Status point 31 (TED6) |
| 32 | , | Status point 32 (LRM1TX) |
| 33 | 1 | Status point 33 (LRM1RX) |


| J8 Signal-To-Pin Relationahip - Continued |  |  |
| :---: | :---: | :---: |
| Pin | I/O | Signal |
|  |  |  |
| 34 | I | Status point 34 (LRM2TX) |
| 35 | I | Status point 35 (LRM2RX) |
| 36 | I | Status point 36 (LRM3TX) |
| 37 | I | Status point 37 (LRM3RX) |
| 38 | I | Status point 38 (LRM4TX) |
| 39 | I | Status point 39 (LRM4RX) |
| 40 | I | Status point 40 (LRM5TX) |
| 41 | I | Status point 41 (LRM5RX) |
| 42 | I | Status point 42 (LRM6TX) |
| 43 | I | Status point 43 (LRM6RX) |
| 44 | I | Status point 44 (GMSA) |
| 45 | I | Status point 45 (TSSP1T) |
| 46 | I | Status point 46 (TSSP1R) |
| 47 | I | Status point 47 (TSSP2T) |
| 48 | I | Status point 48 (TSSP2R) |
| 49 | I | Status point 49 (TRANS1) |
| 50 | I | Status point 50 (TRANS2) |
| 51 |  | Status point 51 - spare |
| 52 | I | Status point 52 - spare |
| 53 | I | Status point 53 - spare |
| 54 | I | Status point 54 - spare |
| 55 | I | Status point 55 - spare |
| 56 | I | Status point 56 - spare |
| $57-79$ | I. | Not used |

h. Connectors J9 (V1 and V2 models only) and J11 (V1 model only). These connectors are used for unbalanced NRZ (TD-660) inputs/outputs. Connector J9 is for groups 1 and 2 and connector J11 is for groups 3 and 4 .


J9 Signal-To-Pin Relationship

| Pin | I/O | Signal |
| :---: | :--- | :--- |
| A | I | Receive data from TD-660 group 1 |
| B | I | Receive data group 1 shield |
| C,D |  | Not used |
| E | O | Unbalanced timing group 1 |
| F | C | Unbalanced timing group 1 shield |
| G | O | Unbalanced timing group 2 |
| H | O | Unbalanced timing group 2 shield |
| J,K | - | Not used |
| L | I | Receive data from TD-660 group 2 |
| M | I | Receive data group 2 shield |
| N | O | Unbalanced data group 1 |
| P | O | Unbalanced data group 1 shield |
| R | O | Unbalanced data group 2 |
| S | O | Unbalanced data group 2 shield |

## 2-5. Rear Connector Signal-To-Pin Relationships - Continued.

J11 Signal-To-Pin Relationship

| Pin | I/o | Signal |
| :---: | :---: | :--- |
| A | I | Receive data from TD-660 group 3 |
| B | I | Receive data group 3 shield |
| C,D | $\cdots$ | Not used |
| E | 0 | Unbalanced timing group 3 |
| F | 0 | Unbalanced timing group 3 shield |
| G | 0 | Unbalanced timing group 4 |
| H | 0 | Unbalanced timing group 4 shield |

J11 Signal-To-Pin Relationship - Continued

| Pin | I/ 0 | Signal |
| :---: | :---: | :--- |
| J,K | -- | Not used |
| L | I | Receive data from TD-660 group 4 <br> M |
| I | Receive data group 4 shield |  |
| N | 0 | Unbalanced data group 3 |
| P | 0 | Unbalanced data group 3 shield |
| R | 0 | Unbalanced data group 4 |
| S | 0 | Unbalanced data group 4 shield |

i. Connector J10 (V3 and V4 models only). Signals to the DLED (in red form) are routed through this connector.

J10 Signal-To-Pin Relationship

| Pin | VO | Signal |
| :---: | :---: | :--- |
| 1 | - | Signal ground |
| 2 | O | DLED data high side (to DLED) |
| $3-5$ | - | Not used |
| 6 | - | Case ground |


j. Connector J12. This connector is used for input/output signals for the Vinson, input/output signals for the dedicated user, and TD-1337(V)/G remote alarm signals.

| J12 Signal-To-Pin Relationship |  |  |
| :---: | :---: | :--- |
| Pin | I/O | Signal |
|  | -- | Ground |
| 1 | I | Vinson data in (from Vinson) |
| 3 | 0 | Vinson data out (to Vinson) |
| 4 | I | Vinson press-to-talk |
| 5 | -- | Not used |
| 6 | I | Loop modem receive data low side |
| 7 | I | Loop modem receive data high side |
| 8 | 0 | Loop modem transmit data low side |
| 9 | 0 | Loop modem transmit data high side |
| 10 | - | Not used |
| 11 | - | Ground |
| 12 | 0 | Receive alarm |
| 13 | 0 | Transmit alarm |
| 14 | -- | Ground |
| $15-22$ | -- | Not used |

## 2-6. Unpacking.

There are no special or unique unpacking requirements for the TD-1337(V)/G. No loose or separate parts or cables are shipped with a TD-1337(V)/G.

## 2-7. Checking Unpacked Equipment.

a. Inspect the equipment for damage incurred during shipment. If the equipment has been damaged, report the damage on SF 364 (Report of Discrepancy).
b. Check the equipment against the packing slip to see if the equipment is complete. Report all discrepancies with the instructions of TM 36-750.
c. Perform (1) through (5) below to check that correct complement of plug-in cards are installed and that red jumper plugs are installed on certain plug-in cards. Report all discrepancies with the instructions of TM 36-750. Correct any discrepancies.
(1) Use cross tip No. 2 screwdriver and loosen 20 fasteners (1) and remove top cover (2).
(2) Check that identification plate (3) has proper model designation (V1, V2, V3, or V4) listed. If model designation is missing or you suspect it is wrong, look at rear connectors to confirm which model you have. (Rear connectors on each model are shown on page 1-6.) Enter correct model designation on plate if it is missing.
(3) Use following list and check that correct complement of plug-in cards are installed for your model. There should be a plug-in card installed in cacti card slot that has an " $X$ ' listed under your model number.

|  | Model |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| Card Slot | V 1 | V 2 | V | V 4 |
| XA1 |  |  | x | x |
| XA2 | x | x | x | x |
| XA3 | x | x |  |  |
| XA4 | x | x | x | x |
| XA5 | x |  | x | x |
| XA6 | x | x | x | x |
| XA7 | x | x | x | x |
| XAB | x | x | x |  |
| XA9 | x | x | x | x |
| XA10 | x | x | x | x |
| XA11 | x | x | x |  |


| Card Slot | Model |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
|  | V1 | V2 | V3 | V4 |
| XA12 | x | x | x | x |
| XA13 | X |  | X | X |
| XA14 | X |  | X |  |
| XA15 | X |  | X |  |
| XA16 | X | x | X | X |
| XA17 | $\mathbf{X}$ |  | X |  |
| XA18 | X |  | X |  |
| XA19 | $\mathbf{x}$ |  | x |  |
| XAZO | X | X | x | X |
| XA21 |  |  |  |  |
| XA22 | $\mathbf{x}$ | X | x | X |

1. FASTENER (20)
2. TOP COVER
3. identification plate


## 2-7. Checking Unpacked Equipment - Continued.

(4) One-at-a-time, pull each below listed card, perform the indicated check, and then reinstall card.

| Card | Card <br> slot | Card part No. | Check |
| :---: | :--- | :--- | :--- |
| A2 | XA2 | SM-D-978560 | That red jumper plugs are installed in J1 through J6. <br> A7 |
| XA7 | SM-D-978585 |  |  |
| A9 | XA9 | SM-D-978555 | That red jumper plugs are installed in J1 and J2. <br> Through J7 for plugs are installed in proper positions in J1 <br> throl as shown on below illustration. If <br> necessary, rearrange red jumper plugs to proper positions |
| A11 | XA11 | SM-D-978550/ <br> That SM-D-978550 card is installed in V1 or V2. |  |
| A20 | XA20 | That SM-D-978630 card is installed in V3 or V4. <br> SM-D-978630 <br> That red jumper plugs are installed in J1 and J2. |  |


nvm Card ag jumper plug arrangement
EL7KCO19
(5) Position top cover (2) on card file and tighten 20 fasteners (1).
d. Check to see whether the equipment has been modified.

## 2-8. installation instructions.

The TD-1337(V)/G is installed with quick-disconnect slides in a 19-inch equipment rack. Perform the "installation" portion of paragraph 2-16 to install a TD-1337(V)/G. After installation, perform the operational test in paragraph 2-17

## Section II. PREVENTIVE MAINTENANCE CHECKS AND SERVICES (PMCS)

There are no PMCS applicable to organizational maintenance.

## Section III. TROUBLESHOOTING

| Subject |  |
| :--- | :--- |
| TD-1337(V)/G Troubleshooting . . . . . . . . . . . . . . . . . . . . . . . . . . . . . |  |

## OVERVIEW

This section contains troubleshooting procedures for isolating a malfunction to an assembly or item that organizational maintenance is authorized to replace. Malfunctions are detected by an abnormal front panel display, by communications from personnel at another equipment location, or by the inability to process orderwire calls.
Always start troubleshooting by using the procedures in paragraph 2-9. The procedures in this paragraph will direct you to replace suspected faulty assemblies, and in some cases direct you to another paragraph to continue troubleshooting. If replacement of the items called out in the troubleshooting procedures does not correct the fault, refer the problem to DS maintenance.
The troubleshooting procedures in this section do not cover faulty system operation that could be caused by improper system configuration data entered in NVM. If you suspect a configuration problem, the orderwire and system configuration data in NVM should be displayed and checked using the display routines in TM 11-7025-221-10.
If during the course of troubleshooting, you observe physical damage (such as broken wiring) beyond your authorized repair capability, report the problem to next higher level of maintenance.

## 2-9. TD-1337(V)/G Troubleshooting.

Use the procedures in this paragraph to start troubleshooting a TD-1337(V)/G. The troubleshooting procedures are In the form of an easy to follow flowchart. The flowchart is arranged so that you will identify and replace the faulty assembly or be directed to another paragraph to continue troubleshooting.
a. Description of Troublshooting Flowchart. The left-hand side of each flowchart page contains a series of decision blocks with each block describing a particular fault condition. Adjacent to each block Is the action to be taken for that fault condition. Following are descriptions of these fault conditions.
(1) POWER AC or DC Indicators Off. Either or both of these indicators being off indicates a power problem.
(2) ALARMS hdicator(s) Lit. There is a block for each ALARMS indicator. One or more of these Indicators will light when the TD-1337(V)/G detects a fault. if more than one indicator is lit, perform the action with the first lit indicator appearing In the flowchart.
(3) Display/Keyboard Problem. Use this block to start troubleshooting when entries made on keyboard are not displayed correctly (or missing) on display.
(4) Dedicated User Problem. There would be no ALARMS indicator lit. Use this block to start troubleshooting when a problem is reported by the dedicated user.
(5) Download To Standby Problem. There would be no ALARMS indicator lit, Use this block to start troubleshooting when it is determined that a download standby routine cannot be performed properly with a standby TD-1337(V)/G.
(6) Orderwire Problem. There would be no ALARMS indicator lit. Use this block to start troubleshooting when you have an orderwire probliem.
(7) Group Problem. There would be no ALARMS indicator lit. Use this block to start troubleshooting when a problem is reported by a earth-side user connected to one of your input/output ports.
(8) Control Te/emetry Problem. There would be no ALARMS indicator lit. Use this block to start troubleshooting when you cannot perform a transmit download routine or receive control telemetry routine Property.
(9) CNCE Reports Loss of CESE. There would be no ALARMS indicator lit. Use this block to start troubleshooting when the CNCE reports a loss of CESE data.
b. Use of Troubleshooting Flowchart. Go to the START entry in the flowchart. Proceed through the blocks until your fault condition is described. if you have more than one fault condition, perform the troubleshooting actions for the first faulot condition appearing in the flowchart. Then, proceed to any remaining fault conditions. Troubleshooting is completed when no fault conditions exist. Some troubleshooting actions direct you to replace more than one assembly. in these cases, replace them one at a time, in the order hated, until fault no longer exists. At the conclusion of troubleshooting, replace any substituted assemblies with the original assemblies (except for faulty ones). Use appropriate replacement procedures as directed in c below.

## 2-9. TD-1337(V)/G Troubleshooting - Continued.

c. Replacement Procedures. When the flowchart directs you to replace an item, replace it by using the instructions for the item as listed in the below chart.

## - © CAUTION $\bullet$

Cooling air flow through TD-1337(V)/G is interrupted when TD-1337(V) is extended out of rack. Remove top cover and limit operating time to one hour when cooling air is not being applied to TD-1337(V)/G. Otherwise, excessive heating condition may occur and cause damage to electrical components.

## NOTES

- Remember that when replacing cards A2, A7, A9, and A20 you must check for certain jumper plugs being installed,
- Remember that when replacing card A9 it may be necessary to re-enter system configuration data.

| Replacement |  |  |
| :--- | :---: | :--- |
| Procedures References |  |  |
| PS1 | Para No. | Remarks |
| AC or DC Indicator | $2-20$ | Replace power supply PS1 in TD-1337(V)/G <br> Replace POWER AC or DC indicator on <br> front panel |
| A1 thru A22 | $2-19$ | Replace plug-in card(s) in card file <br> Remove and install front panel on TD- <br> A23 |
| A23A1 | $2-21$ | 1337(V)/G |
| A23A2 | $2-22$ | Replace display card on front panel <br> A25 |
| TD-1337(V)/G | $2-23$ | Replace keyboard on front panel |
| Replace red CESE assembly |  |  |

NOTE
Use the following instructions only when directed to do so in flowchart.
d. flowchart Supplementary Troubleshooting. Certain faults can inhibit processing and display operations which, in turn, affect diagnostic presentations. Typically, these conditions will light the ALARMS PROCESSOR indicator; or all ALARMS indicators are off and the display cannot be activated. When these conditions exist, and replacement of the assemblies associated with the ALARMS PROCESSOR LIT or DISPLAY/KEYBOARD PROBLEM actions do not correct the problem, you are directed to this subparagraph. At this time, perform the ALARM BUS troubleshooting procedures in paragraph 2-13. These procedures will enable you to find the faulty assembly and correct the problem. When using the procedures in paragraph 2-13 it is not necessary that you replace those assemblies that you have already replaced prior to being directed to this paragraph by the flowchart.

## 2-9. TD-1337(V)/G Troubleshooting - Continued.



## 2-9. TD-1337(V)/G Troubleshooting - Continued



NOTES:

1. IF NVM CHECKSUM ERROR MESSAGE IS DISPLAYED, PERFORM TROUBLESHOOTING IN PARA 2-10.
2. If TD-1337(V)/G WAS NOT OPERATING IN INACTIVE MODE WHEN POWER WAS TURNED OFF, BUT GOES TO INACTIVE MODE WHEN POWER IS TURNED ON, PERFORM TROUBLESHOOTING IN para 2-11.
3. WHEN MULTIPLE ITEMS ARE LISTED TO BE REPLACED, REPLACE THEM ONE AT A TIME IN ORDER LISTED.
4. SET POWER CB TO OFF AND BACK TO ON. IF ALARM INDICATION goEs away, fault is corrected. If alarm indication STILL EXISTS, PERFORM NEXT TROUBLESHOOTING ACTION.
5. PROCEDURES FOR ALARMS RECALL ROUTINE ARE IN TM 11-7025-221-10.
6. DEMUX MEANS REPLACE A dEMUX CARD. REFER TO CONF IGURATION DATA TO DETERMINE WHICH DEMUX IS ASSOCIATED WITH REPORTED FAULT. REPlACE APPROPRIATE CARD.
$\begin{array}{ll}\text { DEMUX } 1=A 16 & \text { DEMUX } 3=A 18 \\ \text { DEMUX } 2=A 17 & \text { DEMUX } 4=A 19\end{array}$
7. buffer means replace an output buffer card. determine WHICH PORT IS ASSOCIATED WITH REPORTED FAULT. REPLACE APPROPRIATE CARD.

PORT: | $1=A 12$ | $4=A 13$ | $7=A 15$ |  |
| ---: | :--- | :--- | :--- |
| 2 | $=$ A12 | $5=A 14$ | $8=$ A15 |
| 3 | $=$ A13 | $6=$ A14 |  |

4. DEMUX (NOTE 6)
B. IF FAULT STILI EXISTS, DIRECT APPLICABLE REMOTE TD-1337(V)/G
TO REPLACE SAME CARDS LISTED
ABOVE. $\qquad$
A. REPLACE
5. AB 4. DEMUX (NOTE 6)
$\begin{array}{ll}\text { 2. } A 7 & \text { 5. All }\end{array}$
6. A6
B. IF FAULT STILL EXISTS, DIRECT APPLICABLE REMOTE TD-1337(V)/G TO REPLACE SAME CARDS LISTED ABOVE.

UNBAL NRZ

A. REPLACE

1. A3 4. BUFFER (NOTE ?
2. A6 5. DEMUX (NOTE 6)
B. IF FAULT STILL EXISTS, DIRECT APPLICABLE REMOTE TO-1337(V)/G TO REPLACE SAME CARDS LISTED ABOVE.

A. REPLACE
3. $A B$
4. A20
5. A16
6. If FAULT STILL EXISTS, DIRECT APPLICABLE REMOTE TO-1337(V)/G TO REPLACE


EL7KCO21

## 2-10. NVM CHECKSUM ERROR Troubleshooting.

Perform the troubleshooting procedures in this paragraph when the NVM CHECKSUM ERROR message is displayed. This message can be displayed when a system mode change is performed to place the TD-1337(V)/G in memory 1 or memory 2 mode of operation. Troubleshooting procedures are in the form of an easy to follow flowchart.
a. Description of Problem. Whenever a system mode change to memory 1 or memory 2 mode is performed, an automatic check is made on data in that NVM memory area. If this check determines that the configuration data has been altered, the NVM CHECKSUM ERROR message is displayed. Configuration data could have been altered by a transient problem or as a result of a faulty plug-in card.
b. Description of Troubleshooting. The NVM CHECKSUM ERROR message will tell you which memory (1 or 2) has the error and which portion of the configuration data (roux or Rmux) is faulty. If MUX is displayed, the flowchart will direct you to re-enter all the configuration data for the selected memory. If RMUX (1, 2, 3, or 4) is displayed, you will be directed to re-enter the configuration data for the Rmux displayed. After the configuration data is entered, you are directed to perform a system mode change. If the mode change is successful, then the NVM CHECKSUM ERROR message was caused by a transient and there are no faulty cards in your TD-1337(V)/G. If the mode change cannot be performed (NVM CHECKSUM ERROR repeats), then you will be directed to replace cards.
c. Use of Troubleshooting Flowchart. Go to the START entry in the flowchart. Perform the actions as directed until the problem is isolated and corrected. If you are directed to replace a card, refer to the plug-in card replacement instructions in paragraph 2-18.

## 2-10. NVM CHECKSUM ERROR Troubleshooting - Continued.



EL $7 \mathrm{KCO22}$

## 2-11. Inactive Mode Change Troubleshooting.

Perform the troubleshooting procedures in this paragraph when the following fault condition is observed:
Message display shows TD-1337(V)/G is operating in INACTIVE MODE when POWER CB is set to ON, but TD-1337(V)/G was operating in another mode when POWER CB was set to OFF. (TD-1337(V)/G should not change mode of operation when power is turned off and on,)
a. Description of Problem. There are two situations that could cause the TD-1337(V)/G to come up in the INACTIVE MODE when power is turned on and you expect it to be operating in some other mode.
(1) Someone turned on your TD-1337(V)/G and changed to INACTIVE MODE or erased data in NVM without telling you. In this case, no hardware fault exists.
(2) Each time the TD-1337(V)/G is turned on, certain checks are automatically made on the data in NVM to ensure that the data has not been altered. If the checks are not successful, configuration data in NVM is erased and the TD-1337(V)/G is placed in the INACTIVE MODE. Configuration data could have been altered by a transient or as a result of a faulty plug-in card.
b. Description of Troubleshooting. The procedures in the flowchart first direct you to perform a system mode change to determine if a fault condition really exists, If the mode change is successful, there is no problem. If the mode change cannot be performed, the procedures then direct you to perform a short configuration routine (enter orderwire configuration data). Power is turned off and then back on. Then a display routine is performed to determine if the entered data was retained by NVM. If the brief routine is successful, then complete configuration data is recentered and further checks performed.
c. Use of Troubleshooting Flowchart. Go to the START entry in the flowchart. Perform the actions as directed until the problem is isolated and corrected. If you are directed to replace a card, refer to the plug-in card replacement instructions in paragraph 2-18.

## NOTE

If your TD-1337(V)/G is connected to a standby TD-1337(V)/G, the POWER CB on the standby must be set to OFF during troubleshooting. When standby is on and your TD-1337(V)/G is off, the standby provides dc power to the NVM circuits on card A9. If your problem is caused by a faulty battery on card A9, you cannot isolate it if the standby is on.

2-11. Inactive Mode Change Troubleshooting - Continued.


## 2-12. Power Distribution Troubleshooting.

Perform the troubleshooting procedures in this paragraph when directed by the TD-1337(V)/G troubleshooting procedures in paragraph 2-9.
a. Description of Problem. POWER DC indicator remains off after POWER DC indicator and power supply PSI have been replaced. This symptom can be caused by a shorting condition in one of the replaceable assemblies. The shorting condition has forced one or more of the power supply dc outputs into an undervoltage state which turns off the POWER DC indicator.
b. Description of Troubleshooting. The procedures in the flowchart first direct you to lift all of the plug-in cards in the card file. If the POWER DC indicator lights after the cards have been lifted, then one of the lifted cards is faulty. One at a time, the cards are seated (installed) in the card file. The card that causes the POWER DC indicator to be off when power is turned on is faulty. If the POWER DC indicator remains off when all the cards are lifted, then the fault is associated with display card A23A1 or red CESE assembly A25.
c. Use of Troubleshooting Flowchart Go to the START entry in the flowchart. Perform the actions as directed until the fault is isolated and corrected. If necessary, refer to the plug-in card replacement instructions in paragraph 2-18. When you are directed to lift a card, extend the two card ejector handles on the edge of the card. This action lifts the card so that the card edge connector is disconnected from the connector pins in the card file. It is not necessary to completely lift the card out of the card file. If none of the replaceable assemblies are faulty, the flowchart will direct you to call next higher level of maintenance.


## 2-13. ALARMS BUS Troubleshooting.

Perform the troubleshooting procedures in this paragraph when directed by the TD-1337(V)/G troubleshooting procedures in paragraph 2-9
a. Description of Problem. Data are exchanged between the microprocessor and the other cards via an eight-bit hi-directional data bus. At regular intervals, a test is automatically performed on the data bus. The test consists of writing data to and reading that data from unused areas of memory on NVM card A9 and display card A23A1. Failure of this test will cause the ALARMS BUS indicator to light. There are four cards (A9, A11, A22, and A23A1) directly involved in conduct of the test. The other cards connected to the data bus can cause a test failure if they have a fault that pulls one or more bits of the data bus low.
b. Description of Troubleshooting. The procedures in the flowchart first direct you to lift, one-at-a-time, those cards not directly involved in conduct of the test. If one of these cards is faulty, a normal power on display will occur when faulty card is lifted and POWER CB is set to ON. If none of these cards are faulty (normal power on display does not occur when ail designated cards are lifted), they are seated (installed) in the card file. Next, you are directed to replace, one-at-a-time, each of the four cards directly involved with conduct of the bus test.
c. Use of Troubleshooting Flowchart. Go to the START entry in the flowchart. Perform the actions as directed until the fault is isolated and corrected. If necessary, refer to the plug-in card replacement instructions in paragraph 2-18 and the display card replacement instructions in paragraph 2-22. When you are directed to lift a card, extend the two card ejector handles on the edge of the card. This action lifts the card so that the card edge connector is disconnected from the connector pins in the card file. It is not necessary to completely lift the card out of the card file. If none of the replaceable assemblies are faulty, the flowchart will direct you to call next higher level of maintenance.


WHEN POHER CB IS SET TO OFF AND BACK TO ON,
IT IS LIKELY THAT ALARMS BUS INDICATOR WILL
no longer be lit. instead, alarms processor
Indicator may be lit and a normal power on oisplay will not be present

## 2-14. How to Use Alarms Recall Data.

When you are directed by the TD-1337(V)/G troubleshooting procedures in paragraph 2-9to "Replace Card(s) Recorded During Alarms Recall", follow the instructions in a below. When you are directed by the troubleshooting procedures to check out a recurring ALARMS MINOR indication, use the troubleshooting procedures in $b$ below.
a. Troubleshooting Based on ALARMS MAJOR Problems. Use the instructions in the flowchart on the facing page. You will find the faulty card faster and with less confusion if you follow these instructions. Flowchart hi-lights are listed below.

- If there are multiple fault conditions, you could have data displayed under both TSSP MAJOR NEW and TSSP MAJOR OLD headings. In this case, merge the recalled data into one list, in alarm number sequence. Each time power is turned off and back on, data recorded under TSSP MAJOR OLD headings will appear under TSSP MAJOR NEW headings. Conversely, performing a second alarms recall routine, without turning power off, will cause data originally appearing under TSSP MAJOR NEW headings to be displayed under a TSSP MAJOR OLD heading.
- If two or more alarm numbers (lines of data) are recorded, start with the lowest alarm number.
- When two or more alarm numbers are recorded, it is very likely that multiple fault conditions exist. In this case, you could replace a card that corrected the first fault, but the ALARMS MAJOR indicator would still be lit due to the second fault. It now becomes necessary to perform an alarms recall routine after each card replacement to determine if the original alarm number is still displayed (first fault corrected or not corrected).
- Replace the cards, one-at-a-time, in the order listed for a given alarm number. If "DEMUX" is included in the listing, it means replace a demux card. Refer to paragraph 2-15 to determine demux card (AI 6 through AI 9) to be replaced.
- If an alarm number does not have a reference designator displayed, go to paragraph 2-15.
- If all cards associated with an alarm number have been replaced and the problem still exists, go to paragraph 2-15
b. Troubleshooting Based On Repeating TSSP MINOR Problems. A faulty condition is indicated when the same alarm number is repeated under the TSSP MINOR heading. Depending on the operating system configuration, the alarm number could repeat in minutes or it could repeat several days apart. When the same alarm number is repeated, perform the troubleshooting procedures as directed in a above; with the following exceptions.
- Ignore block in flowchart that merges TSSP MAJOR NEW and TSSP MAJOR OLD headings into one listing. There is only one TSSP MINOR heading.
- When a card is replaced, observe that ALARMS MINOR indicator is not lit instead of ALARMS MAJOR indicator.
- When a card is replaced, wait a given amount of time for ALARMS MINOR indicator to light. Waiting time should be same as that noted when it was determined that same alarm number is repeating.


## 2-14. How to Use Alarms Recall Data - Continued.



## 2-15. Additional Troubleshooting Procedures.

Use the information in the following chart when directed to do so by another paragraph. This information will be used when one of the following conditions exist:

When all of the cards for an alarm number have been replaced and the fault still exists.

- When "DEMUX" is next card listed as replacement for alarm number being used in troubleshooting.
. There is no reference designator listed after alarm number being used.
a. Description of Additionsl Troubleshooting Chart. All the alarm numbers, associated data, and applicable additional troubleshooting data are listed under the columns described below.
(1) "Alarm No." Column. This column lists all the alarm numbers, in numerical order, that can be displayed.
(2) "Message" Column. This column lists all the data that are displayed with each alarm number. If "Not used" appears, this is an inactive alarm.
(3) "Additional Troubleshooting" Column. Additional troubleshooting actions that can be performed for an alarm number appear in this column.
b. Use of Additions/ Troubleshooting Chart. Use the data in the chart by performing the following steps:
(1) Go to alarm number listed in "Alarm No." column.
(2) Ensure that you have replaced each card listed in the "Message" column for the given alarm number. If "'DEMUX" is listed, refer to "Additional Troubleshooting" column to determine demux card to be replaced.
(3) Replace any cards listed in "Additional Troubleshooting" column. If fault still exists, report problem to next higher level of maintenance.

Additional Troubleshooting Chat

| Display |  | Additional Troubleshooting |
| :---: | :---: | :---: |
| Alarm No. | Message |  |
| 01 | BUS |  |
| 02 | A23A1 |  |
| 03 | A9 |  |
| 04 | A7 |  |
| 05 | A4 |  |
| 06 | A2 |  |
| 07 | A6 |  |
| 08 | A6 |  |
| 09 | A22 |  |
| 10 | A5 |  |
| 11 | LOS1 A3 A7 |  |
| 12 | LOS 1 A 20 | A6, A5 |

## 2-15. Additional Troubleshooting Procedures - Continued.

Additional Troubleshooting Chart - Continued

|  | Display |  |
| :---: | :---: | :---: |
| Alarm No. | Message | Additional Troubleshooting |
| 13 | A6 |  |
| 14 | Not used |  |
| 15 | LOT1 A6 | If port 1 is conditioned diphase, replace A20. If port 1 is unbalanced NRZ, replace A3. |
| 16 | Not used |  |
| 17 | LOS2 A3 A7 |  |
| 18 | Not used |  |
| 19 | A6 |  |
| 20 | Not used |  |
| 21 | LOT2 A6 | If port 2 is unbalanced NRZ, replace A3. |
| 22 | Not used |  |
| 23 | LOS3 A3 A7 |  |
| 24 | LOS3 A20 |  |
| 25 | Not used |  |
| 26 | A6 A5 |  |
| 27 | Not used |  |
| 28 | LOT3 A5 | If port 3 is conditioned diphase, replace A20, If port 3 is unbalanced NRZ, replace A3. |
| 29 | LOS4 A3 A7 |  |
| 30 | Not used |  |
| 31 | Not used |  |
| 32 | A6 A5 |  |
| 33 | Not used |  |
| 34 | LOT4 A5 | If port 4 is unbalanced $N R Z$, replace A3. |
| 35 | Not used |  |
| 36 | LOS5 A20 |  |

## 2-15. Additional Troubleshooting Procedures - continued.

## Additional Troubleshooting Chart - Continued

|  | Display |  |
| :---: | :---: | :---: |
| Alarm No. | Message | Additional Troubleshooting |
| 37 | Not used |  |
| 38 | A6 A5 |  |
| 39 | Not used |  |
| 40 | LOT5 A5 | if port 5 is conditioned diphase, replace A20. |
| 41 | Not used |  |
| 42 | Not used |  |
| 43 | Not used |  |
| 44 | A6 A5 |  |
| 45 | Not used |  |
| 46 | LOT6 A5 |  |
| 47 | Not used |  |
| 46 | Not used |  |
| 49 | Not used |  |
| 50 | A6 A5 |  |
| 51 | Not used |  |
| 52 | LOT7 A5 |  |
| 53 | Not used |  |
| 54 | Not used |  |
| 55 | Not used |  |
| 56 | A6 A5 |  |
| 57 | Not used |  |
| 56 | LOT8 A5 |  |
| 59 | A1 |  |
| 60 | LOT A1 |  |

2-15. Additional Troubleshooting Procedures - continued.
Additional Troubleshooting Chart - Continued

|  | Display | Additional Troubleshooting |  |
| :---: | :---: | :---: | :---: |
| Alarm No. | Message |  |  |
| 61 | A1 A6 A2 |  |  |
| 62 | A1 | A25 |  |
| 63 | A25 |  |  |
| 64 | A8 |  |  |
| 65 | A4 |  |  |
| 66 | A7 |  |  |
| 67 | A2 |  |  |
| 68 | A2 |  |  |
| 69 | A16 |  |  |
| 70 | LOT A16 |  |  |
| 71 | A16 |  |  |
| 72 | A16 A11 |  |  |
| 73 | 0051 |  | Replace A16, A2. Direct remote TD-1337(V)/G supplying SG to replace A6. |
| 74 | A16 |  |  |
| 75 | A16 A8 |  |  |
| 76 | A8 | A16 |  |
| 77 | A4 A16 |  |  |
| 78 | A17 |  |  |
| 79 | LOT A17 |  |  |
| 80 | A17 |  |  |
| 81 | A17A11 |  |  |
| 82 | 0052 |  | Replace A17, A2. Direct remote TD-1337(V)/G supplying SG to replace A6, |
| 83 | A17 |  |  |

## 2-15. Additional Troubleshooting Procedures - Continued.

Additional Troubleshooting Chart - Continued

| Display |  | Additional Troubleshooting |
| :---: | :---: | :---: |
| Alarm No | Message |  |
| 64 | A17 A8 |  |
| 85 | A8 | A17 |
| 86 | A4 A17 |  |
| 87 | A18 |  |
| 88 | LOT A18 |  |
| 89 | A18 |  |
| 90 | A18 A11 |  |
| 91 | 00S3 | Replace A18, A2. Direct remote TD-1337(V)/G supplying SG to replace A6. |
| 92 | AI 8 |  |
| 93 | A18 A8 |  |
| 94 | A8 | A18 |
| 95 | A4 A18 |  |
| 96 | A19 |  |
| 97 | LOT A19 |  |
| 98 | A19 |  |
| 99 | A19A11 |  |
| 100 | 00S4 | Replace A19, A2. Direct remote TD-1337(V)/G supplying SG to replace A6. |
| 101 | A19 |  |
| 102 | A19 A8 |  |
| 103 | A8 | A19 |
| 104 | A4 A19 |  |
| 105 | A12 |  |

## 2-15. Additional Troubleshooting Procedures - Continued.

Additional Troubleshooting Chart - Continued

| Display |  | Additional Troubleshooting |
| :---: | :---: | :---: |
| Alarm No. | Message |  |
| 106 | A12 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 1.' |
| 107 | A3 A12 A7 |  |
| 108 | A20 A12 |  |
| 109 | A12 |  |
| 110 | A12 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 2. |
| 111 | A3 A12 A7 |  |
| 112 | Not used |  |
| 113 | A13 |  |
| 114 | A13 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 3.* |
| 115 | A3 A13 A7 |  |
| 116 | A20 A13 |  |
| 117 | A13 |  |
| 118 | Al 3 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 4.* |
| 119 | A3 A13 A7 |  |
| 120 | Not used |  |
| 121 | A14 |  |
| 122 | A14 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 5. |
| 123 | Not used |  |
| 124 | A20 A14 |  |
| 125 | A14 |  |

## 2-15. Additional Troubleshooting Procedures - Continued.

Additional Troubleshooting Chart - Continued

| Display |  | Additional Troubleshooting |
| :---: | :---: | :---: |
| Alarm No. | Message |  |
| 126 | A14 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 6.* |
| 127 | Not used |  |
| 128 | Not used |  |
| 129 | A15 |  |
| 130 | A15 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 7.* |
| 131 | Not used |  |
| 132 | Not used |  |
| 133 | A15 |  |
| 134 | A15 A22 DEMUX | DEMUX means replace demux card supplying data to your output port No. 8.* |

*Check your local mux configuration data and determine which demux (1, 2, 3, or 4) is assigned to output port reporting the fault condition. When demux number is determined, replace associated demux card. See following list:

$$
\begin{array}{ll}
\text { DEMUX } 1=\text { A16 } & \text { DEMUX } 3=\text { A18 } \\
\text { DEMUX } 2=\text { A17 } & \text { DEMUX } 4=\text { A19 }
\end{array}
$$

## Section IV. MAINTENANCE PROCEDURES

| Subject | Para | Page |
| :---: | :---: | :---: |
| TD-1337(V)/G Removal and Installation Instructions | 2-16 | 2-31 |
| Operational Test | 2-17 | 2-35 |
| Plug-In Card Replacement Instructions | 2-18 | 2-36 |
| POWER AC and DC Indicator Replacement instructions | 2-19 | 2-39 |
| Power Supply Replacement instructions | 2-20 | 2-40 |
| Front Panel Removal and Installation Instructions | 2-21 | 2-42 |
| Display Card Replacement Instructions . | 2-22 | 2-44 |
| Keyboard Replacement Instructions . | 2-23 | 2-46 |
| Red CESE Assembly Replacement Instructions | 2-24 | 2-50 |

## OVERVIEW

Repair of the TD-1337(V)/G consists of replacing the TD-1337(V)/G, a faulty plug-in card, or one of the other items listed above. A replacement action is performed when directed by troubleshooting.
All of the replaceable assemblies, except the red CESE assembly, can be replaced without removing the TD-1337(V)/G from the equipment rack, providing that there is adequate space above the TD-1337(V)/G to remove and install the assemblies.
There are no special cleaning or servicing requirements.
Notify your local users and remote TD-1337(V)/G's in your network when your TD-1337(V)/G is to be turned off for maintenance. This will help them expect and understand any alarm signals and conditions that could occur when your communications functions are interrupted.

## 2-16. TD-1337(V)/G Removal and Installation Instructions.

This task covers:
a. Removal
b. Installation

## INITIAL SETUP

## Applicable Configurations

All models
Tools
Cross-tip screwdriver, No. 2
Hex socket wrench, $3 / 8$-inch opening

## Personnel Required: 2

Tactical Satellite Microwave System operator MOS 26Q
Second person to help support and lift TD1337(V)/G

## Equipment Condition

Notify local users and remote TD-1337(V)/G(s) that your TD-1337(V)/G is being turned off for maintenance.

If installing a replacement TD-1337(V)/G, ensure it was inspected as directed in paragraph 2-7.

## General Safety Instructions

TD-1337(V)/G weighs approximately 62 pounds. Two persons are required to lift and handle it to prevent injury to personnel.
High voltage is applied to TD-1337(V)/G when rack power is on. Turn off rack power when removing or installing a TD-1337(V)/G.

## 2-16. TD-1337(V)/G Removal and Installation Instructions - Continued.

| Location/tem | Action | Remarks |
| :---: | :---: | :---: |
|  | $\bullet$ WARNING | $\bullet$ |

High voltage is applied to TD-1337(V)/G when rack power is on. To prevent a serious shock hazard, that could result in DEATH or SERIOUS INJURY turn off rack power when removing or installing a TD-1337(V)/G.

## Removal

1. POWER CB (1)
2. Rack power
3. 8 fasteners (2)
4. TD-1337(V)/G

Set to OFF
Turn off
Loosen
Extend

Turn counterclockwise to loosen.
Use handles (3) and pull TD-1337(V)/G out of rack until locks (4) in slides (5) engage.

When locks on slides are bypassed, there are no mechanical restraints to prevent TD-1337(V)/G from rollin ${ }^{9}$ out of slides and falling. Use a second person to help you support TD-1337(V)/G in the following steps to prevent possible injury to yourself and others.

NOTE


If cables 'are not accessible for steps 5 and 6, release locks (4) and extend TD-1337(V)/G as necessary to reach and disconnect cables.
5. Cables connected to Disconnect all cables except ground rear of $\quad$ cable to El (6). TD-1337(V)/G
6. Ground cable con-

Disconnect
netted to El (6)

Check each cable to see if mating case connector is marked on it. If not, tag cable to identify its mating case connector.
Place flat washer (10), lockwasher (9), and wingnut (8) back on El after ground cable is removed. Install spring pin (7).

TD-1337(V)/G weighs approximately 62 pounds. Have another person help you lift and support it to prevent injury to yourself and others.
7. $\mathrm{TD}-1337(\mathrm{~V}) / \mathrm{G}$

Remove using two persons.
If not released, release two locks (4) and then pull TD-1337(V)/G from slides (5).

## 2-16. TD-1337(V)/G Removal and Installation Instructions - Continued.



## 2-16. TD-1337(V)/G Removal and Installation Instructions - Continued.

| Location/item | Action | Remarks |
| :---: | :---: | :---: |
| Installation | I |  |
| 8. TD-1337(V)/G | Check that proper model will be installed. | Check identification plate (11) on replacement TD-1337(V)/G to ensure that proper model (V1, V2, V3, or V4) is being installed. If model designation is missing or you suspect it is wrong, look at rear connectors to confirm which model you have. (Rear connectors on each model are shown on page 1-8.) Enter correct model designation on plate if it is missing. |
| 9. TD-1337(V)/G |  | Position slides (5) in rack slides and push in until locks (4) engage. |

When locks on slides are bypassed; there are no mechianical restraints to prevent TD-1337(V)/G from rolling out of slides and falling. If locks are bypassed in steps 10 and 11, use a second person to help you support TD-1337(V)/G to prevent possible injury to yourself and others.

## NOTE



If cables-and connectors are not accessible for steps 10 and 11, release locks and extend TD-1337(V)/G as necessary to reach and connect cables.
10. Ground cable for El (6)
11. System cables
12. $\mathrm{TD}-1337(\mathrm{~V}) / \mathrm{G}$
13. 8 fasteners (2)
14. Rack power
15. POWER CB (1)

Connect

Connect

## Close

Tighten
Turn on
a. Set to ON.
b. If TD-1337(V)/G is being installed because red CESE assembly was replaced, check that fault is corrected.
c. If TD-1337(V)/G being installed is a replacement, perform operational test in para 2-17.

Remove spring pin (7), wingnut (8), lock washer (9), and flat washer (10) from E1. Install ground cable. Re-install washers, wingnut, and spring pin.
Connect cables to rear of TD-1337(V)/G as designated by system configuration.
Release locks (4). Use handles (3) and push TD-1337(V)/G into rack.

Check that POWER AC and DC indicators are lit.
Correct configuration data will be in NVM.

TD-1337(V)/G will be configured for system operation when operational test is performed.

## 2-17. Operational Test.

Perform the following operational test on a newly installed TD-1337(V)/G to verify it is operating properly in its assigned system configuration.

NOTE
If normal indication is not obtained for any step, refer to troubleshooting procedures in paragraph 2-9

Operational Test

| Step | Action | Normal indication |  |
| :---: | :---: | :---: | :---: |
| 1 | Set POWER CB to ON. | POWER AC and DC indicators are lit. | f indicators are not lit, check that rack power is |
| 2 | Check displayed message. | POWER ON SYSTEM IS IN* MODE |  |
| 3 | Check ALARMS indicators. | All ALARMS indicators are |  |
| 4 | Perform display test routine. | Keyboard responses and message displays are normal, |  |
| 5 | Obtain and enter configuration data in TD-1337(V)/G. | Keyboard responses and message displays are normal. |  |
| 6 | Perform system mode change to place TD-1337(V)/G in system operation. | Message display confirms TD$1337(\mathrm{~V}) / \mathrm{G}$ is operating in selected mode. |  |
|  |  | NOTE |  |

## 2-18. Plug-In Card Replacement Instructions.

This task covers:
a. Removal
b. Installation

## INITIAL SETUP

Applicable Configurations
All models
Tools
Cross-tip screwdriver, No. 2

Equipment Condition
Notify local users and remote TD-1337(V)/G(s) that your TD-1337(V)/G is being turned off for maintenance.

General Safety Instructions

|  |  |  |
| :---: | :---: | :---: |
|  | - - CAUTION |  |

## 2-18. Plug-In Card Replacement Instructions - Continued.

| Location/ltem | I | Action | Remarks |
| :--- | :--- | :--- | :--- |
| Installation |  |  |  |
|  | NOTES |  |  |

- Before installing a card in card slot XA2, XA7, or XA20, check that card has proper number of red jumper plugs installed as listed below:

XA2 - SSV card A2 has plugs in J1 thru J6
XA7-16 DVOW card A7 has plugs in J1 and J2
XA20 - Group modem card A20 has plugs in J1 and J2

- When installing NVM card A9 in card slot XA9, check that card has 7 red jumper plugs properly installed for your model as shown on illustration on bottom of next page. jumper plugs.

6. Card slots XA1 thru XA22
7. POWER CB (1)
8. Plug-in cards that were replaced before faulty card was replaced.

Install replacement plug-in card in appropriate card slot.

Set to ON and check if fault causing card replacement has been corrected.
necessary, rearrange

Slide card into guides in card slot and seat card in connector by pressing down on ejector handles (7). Card is seated when handles are parallel to adjacent handles.
a. If NVM card A9 was replaced, system configuration data must be entered in TD-1337(V)/G. Use procedures in TM 11-7025-221-10.
b. If fault is not corrected, perform next action as directed in troubleshooting procedure that directed this card replacement.
c. If fault is corrected, go to step 8.

If only one card was replaced, and it was the faulty one, go to step 9.
a. Set POWER CB to OFF.
b. Remove any replacement cards and re-install original good cards.
c. Set POWER CB to ON.


## 2-18. Plug-In Card Replacement Instructions - Continued.

| Location/Item | Action | Remarks |
| :---: | :---: | :---: |
| Installation - Continued |  |  |
| 9. Top cover (5) | Inspect pads (8) and gasket (9). | Perform following checks and notify next higher level of maintenance of any problems. <br> 1. Check that there are no rips, tears, or missing chunks of gasket or pad. <br> 2. Check that bonded surfaces of gasket and pads are not pulled away from cover surface. |
| 10. Top cover (5) | Install | Place cover on TD-1337(V)/G and tighten 20 fasteners (6). |
| 11. TD-1337(V)/G | close | Release locks (4). Use handles (3) and push TD-1337(V)/G into rack. |
| 12. 8 fasteners (2) | Tighten |  |


nvm card ag jumper plug arrangement

## 2-19. POWER AC and DC Indicator Replacement Instructions.

This task covers:
a. Removal
b. Installation

## INITIAL SETUP

## Applicable Configurations

## Equipment Condition <br> Notify local users and remote TD-1337(V)/G(s) that your TD-1337(V)/G is being turned off for maintenance.

Tools
None
General Safety Instructions
Personnel Required: 1
Tactical Satellite Microwave System Operator MOS 26Q

## Removal

1. POWER CB (1)
2. Lens (2 or 4) for indicator being replaced
3. Indicator (3 or 5) being replaced

## Installation

| 4. Indicator (3 or 5) | Install | Press it straight into housing. |
| :--- | :--- | :--- |
| S. Lens (2 or 4) | Install | Turn clockwise to install. |
| 6. POWER CB (1) | Set to ON. Cheek that POWER AC | If indicators do not light, refer |
|  | and DC indicators are lit. | to troubleshooting procedures (para 2-9). |

1. Power cb
2. AC INDICATOR LENS
3. AC INDICATOR
4. DC INDICATOR LENS
5. DC INDICATOR

Turn counterclockwise to remove.

Pull it straight out of housing.

Press it straight into housing. Turn clockwise to install.
If indicators do not light, refer to troubleshooting procedures (para 2-9).


## 2-20. Power Supply Replacement Instructions.

This task covers:
a. Removal
b. Installation

INITIAL SETUP
Applicable Configurations
All models

## Tools

Hex socket wrench, $3 / 8$-inch opening
Torque wrench with $3 / 8$-inch socket

## Equipment Condition

Notify local users and remote TD-1337(V)/G(s) that your TD-1337(V)/G is being turned off for maintenance.

## General Safety instructions

None.

Personnel Required: 1
Tactical Satellite Microwave System Operator MOS 26Q

| Location/tem | Action | Remarks |
| :---: | :---: | :---: |
| Removal |  |  |
| 1. POWER CB (1) | Set to OFF |  |
| 2. 8 fasteners (2) | Loosen | Turn counterclockwise to loosen. |
| 3. TD-1337(V)/G | Extend | Use handles (3) and pull TD-1337(V)/G out of rack until locks (4) engage. |
| 4. 16 fasteners (5) | Loosen | Turn counterclockwise to loosen. |
| 5. Power supply (6) | Remove | Use handle (7) and lift power supply from case. |
| Installation |  |  |
| 6. Gasket (8) | Inspect | Perform following checks and notify next higher level of maintenance of any problems. <br> 1. Check that there are no rips, tears, or missing chunks in gasket. <br> 2. Check that bonded surface of gasket has not pulled away from case. |
| 7. Power supply (6) | Install | Use handles (7) and lower evenly into case so that guide pins mate with alignment holes of case connector. |
| 8. 16 fasteners (5) | Tighten. Torque to 8 to 10 inchpounds. | Loosely install all fasteners and then torque fasteners. |
| 9. $\mathrm{TD}-1337(\mathrm{~V}) / \mathrm{G}$ | Close | Release locks (4). Use handles (3) and push TD-1337(V)/G into rack. |
| 10. 8 fasteners (2) | Tighten |  |
| 11. POWER CB (1) | Set to ON. Check that POWER $A C$ and $D C$ indicators are lit. | If indicators do not light, refer to troubleshooting. |

## 2-20. Power Supply Replacement Instructions - Continual.

1. POWER CB
2. FASTENER (8)
3. HANDLE (2)
4. LOCK (2)
5. FASTENER (16)
6. POWER SUPPLY PSI
7. HANDLE (2)
8. GASKET

EL7KCO31

## 2-21. Front Panel Removal and Installation Instructions.

This task covers:
a. Removal
b. Installation

INITIAL SETUP
Applicable Configurations
All models
Tools
Cross-tip screwdriver, No. 2
Hex socket wrench, $3 / 8$-inch opening
Personnel Required: 2
Tactical Satellite Microwave System Operator MOS 26Q
Second person to help support front panel

## Equipment Condition

Notify local users and remote TD-1337(V)/G(s) that your TD-1337(V)/G is being turned off for maintenance.

## Genera/ Safety Instructions

High voltage is applied to front panel when rack power is on. Turn off rack power when removing or installing a front panel.

| Location/tem | Action | Remarks |
| :--- | :---: | :---: |
|  | $\bullet$ WARNING $\bullet \bullet$ |  |

High voltage is applied to front panel when rack power is on. To prevent a serious shock hazard that could result in DEATH or SERIOUS INJURY, turn off rack power when removing or installing a front panel.

## Removal

1. POWER CB (1)
2. Rack power
3. 8 fasteners (2)
4. 10 sets of screws
(3) and washers (4)
5. 3 connectors ( 6 , 7, and 8)
6. Front panel (9)

Set to OFF
Turn off
Loosen
Support front panel and remove screws and washers. Use two persons.

Disconnect

Transport to designated work area.

Turn counterclockwise to loosen.
Second person support front panel by handles (5) to prevent placing strain on 3 cables attached to front panel.
Connector (8) has a slide lock that must be opened before it can be removed from case connector.

## 2-21. Front Panel Removal and Installation Instructions - Continued.

| Location/ltem |  | Remarks |
| :--- | :---: | :---: |
| Installation <br> 7. Gasket (10) | Inspect | Perform following checks and notify next <br> higher level of maintenance of any prob- <br> lems. <br> 1. Check that there are no rips, tears, <br> or missing chunks in gasket. |
| 2. Check that bonded surface of gas- |  |  |
| ket has not pulled away from case. |  |  |

Support front panel near TD1337(V)/G using two persons,

Connect

Loosely install all screws and washers and then tighten.
Tighten
Turn on
Set to ON. Check that fault which caused front panel removal has been corrected.

Perform following checks and notify next higher level of maintenance of any problems.

1. Check that there are no rips, tears, or missing chunks in gasket.
ket has not pulled away from case.
2. 10 sets of screws
(3) and washers
(4)
3. 8 fasteners (2)
4. Rack power
5. POWER CB
(1)
6. POWER (1)
7. 3 connectors (6, 7, and 8)

A23P1 (6) mates with A24J2.
A23P2 (8) mates with A24J14.
W1P1 (7) mates with A24J1.
a. If fault has been corrected,

TD-1337(V)/G is operational.
b. If fault still exists, perform next action as directed in troubleshooting procedures (para 2-9).


## 2-22. Display Card Replacement Instructions.

This task covers:
a. Removal
b. installation

INITIAL SETUP
Applicable Configurations
All models

## Tools

Cross-tip screwdriver, No. 2
Hex socket wrench, $3 / 6$-inch opening
Hex socket wrench, $5 / 16$-inch opening
Torque wrench with $3 / 8$-inch and $5 / 16$-inch sockets

Personnel Required: 1
Tactical Satellite Microwave System Operator MOS 26Q

## Equipment Condition

Front panel removed from TD-1337(V)/G (para 2-21).
General Safety Instructions
None

| Location/Item | Action | Remarks |
| :---: | :---: | :---: |
| Removal |  |  |
| 1. 3 sets of screws and washers (1 thru 3) | Remove | 1. Retain all hardware removed in this and following steps. <br> 2. These are screws in capacitor bracket (17). |
| 2. 5 sets of screws and washers (4 thru 6) | Remove | These are rest of screws in display card A23A1 (28). |
| 3. Connector (7) | Disconnect | Retain cable W 1. |
| 4. Connector (8) | Disconnect |  |
| 5. 2 sets of nuts, washers, and terminal lugs (9 thru 16) | Remove | Do not unsolder terminal lugs (11 and 15). |
| 6. Capacitor bracket (17) | Remove |  |
| 7. 2 sets of screws, nuts, washers, and terminal lugs (18 thru 27) | Remove |  |
| 8. Display card (28) | Remove |  |

## 2-22. Display Card Replacement Instructions - Continued.

Location/ltem

Action
Remarks
. SCREW (3)
2. LOCK WASHER (3)
3. FLAT WASHER (3)
4. SCREW (5)
5. LOCK WASHER (5)
6. FLAT WASHER (5)
7. CONNECTOR (PI END OF CABLE W1)
8. CONNECTOR A23A2PI (PART OF KEYBOARD)
9. NUT
10. LOCK WASHER
11. TERMINAL LUG (+ LEAD OF CAPACITOR)
2. FLAT WASHER
3. NUT
14. LOCK WASHER
15. TERMINAL LUG (- LEAD OF CAPACITOR)
16. FLAT WASHER
17. CAPACITOR BRACKET
18. NUT (THREADED SPACER)
19. INTERNAL TOOTH LOCK WASHER
20. TERMINAL LUG (+5V)
21. FLAT WASHER
22. SCREW
23. NUT (THREADED SPACER)
24. INTERNAL TOOTH LOCK WASHER
25. TERMINAL LUG (GROUND)
25. TERMI WAL 26
27. SCREW
28. DISPLAY CARD A23AI
29. CABLE CLAMP


## 2-22. Display Card Replacement instructions - Continued.

| Location/Item | Action | Remarks |
| :---: | :---: | :---: |
| Installation |  |  |
| 9. Replacement display card (28) and 2 sets of screws, nuts, washers, and terminal lugs (18 thru 27) | Install and torque nut (18) to 25 to 30 inch-pounds and and nut (23) to 16 to 18 inch-pounds. | Assemble in sequence shown on page 2-45. |
| 10. Capacitor bracket (17) | Install |  |
| 11. 2 sets of nuts, washers, and terminal lugs (9 thru 16) | Install | Assemble in sequence shown on page 2-45. |
| 12. Connector (8) | Connect | A23A2P1 mates with J2 on display card. |
| 13. Connector (7) | Connect | W1P1 mates with J1 on display card. |
| 14, 5 sets of screws and washers (4 thru 6) | Install and torque nut (9) to 25 to 30 inch-pounds and nut (13) to 16 to 18 inch-pounds. | Align holes in display card with standoffs on rear of front panel and install, but do not tighten screws (4). Ensure that cable clamp (29) is installed. |
| 15. 3 sets of screws and washers (1 thru 3) | Install | Install and tighten. |
| 16. 5 screws (4) | Tighten | Tighten previously installed screws (4). |
| 17. Front panel | Install | Install front panel in TD-1337(V)/G (para 2-21). |

## 2-23. Keyboard Replacement Instructions.

This task covers:
a. Removal
b. Installation

| INITIAL SETUP |  | Personnel Required: 1 |
| :---: | :---: | :---: |
| Applicable Configurations |  | Tactical Satellite Microwave System Operator MOS 26Q |
| Tools |  | Equipment Condition |
| Cross-tip screwdriver, No. 2 |  | Front panel removed from TD-1337(V)/G (para 2-21). |
| Torque wrench with $5 / 16$-inch socket |  | General Safety Instructions |
|  |  | None |
| Location/ltem | Action | Remarks |
| Removal |  |  |
| 1. 3 sets of screws and washers (1 thru 3) | Remove | 1. Retain all hardware removed in this and following steps. <br> 2. These are screws in capacitor bracket (14). |
| 2. 5 sets of screws and washers (4 thru 6) | Remove | These are rest of screws on display card A23A1 (9). |
| 3. Connector (7) | Disconnect |  |
| 4. Display card (9) | Position out of way | Carefully lay display card back on table mat to extent of service loop in wiring. |
| 5. 6 sets of nuts and washers (10 and 11) | Remove |  |
| 6. Keyboard (12) | Remove | Turn connector (7) to align with slot in front panel. |
| Installation |  |  |
| 7. Keyboard (12) | Install and torque nuts (1 O) to 4 to 5 inch-pounds. | Insert keyboard connector (7) through slot in front panel and then attach keyboard to panel using 6 sets of nuts and washers (10 and 11). |
| 8. Connector (7) | Connect | Keyboard connector (7) mates with J2 on display card. |

2-23. Keyboard Replacement Instructions - Continued.

| Location/ltem |  | Action |
| :--- | :--- | :--- |
| Installation - Continued |  | Remarks <br> 9. Display card (9) <br> Align holes in display card (9) with stand- <br> offs on rear of front panel. Install, but <br> do not tighten, 5 sets of screws and <br> washers (4 thru 6). Ensure cable clamp <br> (13) is installed. Install 3 sets of screws <br> and washers (1 thru 3). Tighten screws <br> (1 and 4). <br> Install front panel in TD-1337(V)/G (para <br> $2-21)$. |
| 10. Front panel |  |  |



## 2-24. Red CESE Assembly Replacement Instructions (V3 and V4 Models).

This task covers:
a. Removal
b. Installation
INITIAL SETUP
Applicable Configurations
V3 and V4 models only
Took
Cross-tip screwdriver, No. 2
Material Required
Sealing compound (item 1, Appendix C)

## Personnel Required: 1 <br> Space Communications Systems Equipment Operator Specialist AFSC 304X6 <br> Equipment Condition <br> TD-1337(V)/G removed from rack (para 2-1 6).

| Looation/item | Action | Remarks |
| :---: | :---: | :---: |
| Removal |  |  |
| 1. Bottom cover (1) | Remove | Loosen 28 fasteners (2) and remove bottom cover (1). |
| 2. Red CESE assembly connector (3) | Disconnect | Carefully pull connector (3) from pins 1-18 of XA1 on bottom of backplane. |
| 3. Red CESE assembly (4) | Remove | Remove 4 sets of screws and washers ( 5 and 6 ). Then carefully work red CESE assembly (4) out of case. |
| Installation |  |  |
| 4. Screws (5) | Clean | Clean threads of 4 screws (5). Then place sealing compound (item 1, Appendix C) on threads. |
| 5. Red CESE assembly (4) | Install | Carefully work red CESE assembly (4) into case. Attach with 4 sets of screws and washers (5 and 6). |
| 6. Red CESE assembly connector (3) | Connect | Carefully push connector (3) onto pins 1-16 of XA1. There is a keying plug (pin 5) to ensure connector mates with correct pins on XA1. |
| 7. Gasket (7) | Inspect | Perform following cheeks and notify next higher level of maintenance of any problems. <br> 1. Check that there are no rips, tears, or missing chunks in gasket. <br> 2. Check that bonded surface of gasket has not pulled away from bottom cover. |

2-24. Red CESE Assembly Replacement Instructions (V3 and V4 Models) - Continued.

| Location/tem | Action | Remarks |
| :--- | :---: | :---: |
| Installation - Continued |  |  |
| 8. Bottom cover (I) | Install | Place cover on TD-1337(V)/G and tighten <br> 28 fasteners (2). <br> Install TD-1337(V)/G in rack (para 2-16). |
| 9. TD-1337(V)/G | Install |  |



1. BOTTOM COVER
2. FASTEMER (28)
3. RED CESE CONNECTOR A25PI
4. RED CESE ASSEMBLY A25
5. SCREW (4)
6. FLAT WASHER (4)
(

## Section v. Preparation FOR STORAGE OR SHIPMENT

| Subject |  | Para | Page |
| :---: | :---: | :---: | :---: |
| General |  | 2-25 | 2-52 |
| Packaging Requirements |  | 2-26 | 2-52 |
| Storage Requirements |  | 2-27 | 2-53 |

## 2-25. General.

This section contains the special instruction required for preparing the equipment for storage or shipment. Packaging and packing materials must conform to the requirements in SB 38-100, Preservation, Packaging, pocking and Marking Materials, Supplies, and Equipment Used by the Army.

## 2-26. Packaging Requirements.

The packaging requirements for a TD-1337(V)/G, power supply PS1, and the other replaceable assemblies are described below.
a. TD-1337(V)/G. The TD-1337(V)/G case is ruggedized, but it is not waterproof. The TD-1337(V)/G is transportable, plug-in cards are firmly seated in a shock and vibration-resistant card" file. There are no cables or separate parts to be packaged with a TD-1337(V)/G. A technical manual shipped with a TD-1337(V)/G is packaged and shipped as described below.

## - WARNING

TD-1337(V)/G weighs approximately 62 pounds. Have another person help you lift and support it to prevent injury to yourself and others.
(1) A technical manual shipped with a TD-1337(V)/G will be wrapped and sealed in waterproof material.
(2) TD-1337(V)/G will be wrapped and sealed in waterproof barrier material before it is placed in a container for storage or shipment.
b. Power Supply PS1. Power supply is ruggedized, but it is not waterproof. There are no cables or separate parts to be packaged with the power supply, It should be wrapped and sealed in waterproof barrier material before it is placed in a container for shipment or storage.
c. Plug-in Cards, Display Card, and Red CESE Assembly.

## - - CAUTION • •

NVM card A9 contains a battery. When placing this card in a static-shielding bag, ensure printed wiring surfaces or connector pins on card do not make contact with any conductive surfaces. It is possible that contact with a conductive surface could provide a shorting condition that could discharge the battery.

Plug-in cards, display card, and red CESE assembly must be placed in static-shielding bags prior to shipment or storage. Use static-shielding bag from which spare assembly was removed. If bag is missing or damaged, obtain a new bag. Use a static-shielding bag (such as 3M Type 2100) which has the following characteristics:

- Conductive outer layer (surface resistivity of 104 ohms/sq)
- Non-conductive inner layer (surface resistivity of $10^{12} \mathrm{ohms} / \mathrm{sq}$ )
- High tear and puncture resistance
- High tensile and dielectric strength.


## 2-27. Storage Requirements.

a. TD-1337(V)/G.
(1) Storage Conditions. In addition to the following requirements, an unpackaged TD-1337(V)/G must be stored in a closed sheltered area to protect it from the elements.
Temperature . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 7 . $756^{\circ} \mathrm{C}$ ) to $+160^{\circ} \mathrm{F}\left(+71^{\circ} \mathrm{C}\right)$
Relative humidity ............................................................................................... Low as $5 \%$ in air temperature of $+120^{\circ} \mathrm{F}\left(+49^{\circ} \mathrm{C}\right)$. High as $100 \%$ between air temperature of $-25^{\circ} \mathrm{F}\left(-32^{\circ} \mathrm{C}\right)$ to $+86^{\circ} \mathrm{F}\left(+30^{\circ} \mathrm{C}\right)$ with condensation at all temperatures lower than $+86^{\circ} \mathrm{F} \quad\left(+30^{\circ} \mathrm{C}\right)$.
Salt atmosphere $\qquad$ No greater than encountered during coastal service and ocean transport.
Altitude. Up to 50,000 feet above sea level.
Tropical renditions No greater than encountered in tropical areas including fungus laden air.
(2) Administrative Storage. Refer to TM 740-90-1 for procedures, forms, records, and inspections required during administrative storage of TD-1337(V)/G.
(3) Intemediate or Long Term Storage. TD-1337(V)/G must be packaged as described in paragraph 2-26 for intermediate or long term storage when it is not stored as part of a shelter configuration.
b. Plug-in Cards, Display Cord, and Red CESE Assembly. These items all contain ESDS components. All spores must be stored in static-shielding bags to prevent possible damage to components.

## - - CAUTION

Failure to store items in static-shielding bags could cause them to be damaged by static electricity.

## APPENDIX A REFERENCES

| DA Pam 310-1 | Consolidated Index of Army Publications and Blank Forms. |
| :---: | :---: |
| FM 21-11 | First Aid for Soldiers. |
| SB 38-100 | Preservation, Packaging, Packing and Marking Materials, Supplies, and Equipment Used by the Army. |
| SB 700-20 | Army Adopted/Other Items Selected for Authorization/List of Reportable Items. |
| TM 11-5805-382-12 | Operator's and Organizational Maintenance Manual: Multiplexer TD-660/G (NSN 5805-00-930-8079), TD-660A/G and TD-660B/G (5820-00-928-3382). |
| TM 11-5805-383-12 | Operator's and Organizational Maintenance Manual: Multiplexer TD-754/G (NSN 5820-00-930-8078) . |
| TM 11-7025-202-12 | Operator's and Organizational Maintenance Manual for Multiplexer TD-976/G (NSN 7025-01 -048-\%78) and Pulse Form Restorer TD-982/G (7025-01-061-1 245). |
| TM 11-7025-221-10 | Operator's Manual, Multiplexer, Digital TD-1337(V)/G. |
| TM 11-7025-221-20P | Organizational Maintenance Repair Parts and Special Tools List for Multiplexer, Digital TD-1337(V)/G. |
| TM 38-750 | The Army Maintenance Management Systems (TAMMS). |
| TM 4700-15-1-1/D | The Marine Carps Maintenance Records and Procedures. |
| TM 740-90-1 | Administrative Storage of Equipment. |
| TM 750-244-2 | Procedures for Destruction of Electronics Material To Prevent Enemy Use (Electronic: Command). |
| T.O. 00-20-2 | Maintenance Data Collection System. |

## APPENDIX B <br> MAINTENANCE ALLOCATION CHART

## Section I. INTRODUCTION

## B-1. General.

a. This section provides a general explanation of all maintenance and repair functions authorized at various maintenance categories,
b. The Maintenance Allocation Chart (MAC) in section II designates overall authority and responsibility for the performance of maintenance functions on the identified end item or component. The application of the maintenance functions to the end item or component will be consistent with the capacities and capabilities of the designated maintenance categories.
c. Section III lists the tools and test equipment (both special tools and common tool sets) required for each maintenance function as referenced from section II.
d. Section IV contains supplemental instructions and explanatory notes for a particular maintenance function.

## B-2. Maintenance Functions.

Maintenance functions will be limited to and defined as follows:
a. Inspect. To determine the serviceability of an item by comparing its physical, mechanical, and/or electrical characteristics with established standards through examination (e.g., by sight, sound, or feel).
b. Test, To verify serviceability by measuring the mechanical, pneumatic, hydraulic, or electrical characteristics of an item and comparing those characteristics with prescribed standards.
c. Service. Operations required periodically to keep an item in proper operating condition, i.e., to clean (includes decontaminate, when required), to preserve, to drain, to paint, or to replenish fuel, lubricants, chemical fluids, or gases.
d. Adjust. To maintain or regulate, within prescribed limits, by bringing into proper or exact position, or by setting the operating characteristics to specified parameters.
e. Aline. To adjust specified variable elements of an item to bring about optimum or desired performance.
f. Calibrate. To determine and cause corrections to be made or to be adjusted on instruments or test, measuring, and diagnostic equipments used in precision measurement. Consists of comparisons of two instruments, one of which is a certified standard of known accuracy, to detect and adjust any discrepancy in the accuracy of the instrument being compared.
g. Remove/Install. To remove and install the same item when required to perform service or other maintenance functions. Install may be the act of emplacing, seating, or fixing into position a spare, repair part, or module (component or assembly) in a manner to allow the proper functioning of an equipment or system.
$h$. Rep/ace. To remove an unserviceable item and install a serviceable counterpart in its place. "Replace" is authorized by the MAC and is shown as the 3d position code of the SMR code.
i. Repair. The application of maintenance services, including fault location/troubleshooting, removal/installation, and disassembly/assembly procedures, and maintenance actions to identify troubles and restore serviceability to an item by correcting specific damage, fault, malfunction, or failure in a part, subassembly, module (component or assembly), end item, or system.
j. Overhaul. That maintenance effort (service/action) prescribed to restore an item to a completely serviceable/operational condition as required by maintenance standards in appropriate technical publications (e.g., DMWR). Overhaul is normally the highest degree of maintenance performed by the Army. Overhaul does not normally return an item to like new condition.

## B-2. Maintenance Functions - Continued.

k. Rebuild. Consists of those services/actions necessary for the restoration of unserviceable equipment to a like new condition in accordance with original manufacturing standards. Rebuild is the highest degree of materiel maintenance applied to Army equipment. The rebuild operation includes the act of returning to zero those age measurements (hours/miles, etc.) considered in classifying Army equipment/components.

## B-3. Explanation of Columns in MAC, Section II.

a. Column 1, Group Number. Column 1 lists functional group code numbers, the purpose of which is to identify maintenance significant components, assemblies, subassemblies, and modules with the next higher assembly. End item group number shall be "00."
b. Column 2, Component/Assernbly. Column 2 contains the names of components, assemblies, subassemblies, and modules for which maintenance is authorized.
c. Column 3, Maintenance Function. Column 3 lists the functions to be performed on the item listed in Column 2. (For detailed explanation of these functions, see paragraph B-2.)
d. Column 4, Maintenance Category. Column 4 specifies, by the listing of a work time figure in the appropriate subcolumn(s), the category of maintenance authorized to perform the function listed in Column 3. This figure represents the active time required to perform that maintenance function at the indicated category of maintenance. If the number or complexity of the tasks within the listed maintenance function vary at different maintenance categories, appropriate work time figures will be shown for each category. The work time figure represents the average time required to restore an item (assembly, subassembly, component, module, end item, or system) to a serviceable condition under typical field operating conditions. This time includes preparation time (including any necessary disassembly/assembly time), troubleshooting/fault location time, and quality assurance/quality control time in addition to the time required to perform the specific tasks identified for the maintenance functions authorized in the maintenance allocation chart. The symbol designations for the various maintenance categories are as follows:

| C | Operator or crew |
| :---: | :---: |
| 0 | Organizational maintenance |
| F | Direct Support Maintenance |
| H | General Support Maintenance |
| D | Depot maintenance |

e. Column 5, Tools and Equipment. Column 5 specifies, by code, those common tool sets (not individual tools) and special tools, TMDE, and support equipment required to perform the designated function.
f. Column 6, Remarks. This column shall, when applicable, contain a letter code, in alphabetic order, which shall be keyed to the remarks contained in Section IV.

## B-4. Explanation of Columns in Tool and Test Equipment Requirements, Section III.

a. Column 7, Reference Code. The tool and test equipment reference code correlates with a code used in the MAC, Section II, Column 5.
b. Column 2, Maintenance Category. The lowest category of maintenance authorized to use the tool or test equipment.
c. Column 3, Nomenclature. Name or identification of the tool or test equipment.
d. Column 4, National Stock Number. The National stock number of the tool or test equipment.
e. Column 5, Too/ Number. The manufacturer's part number.

## B-5. Explanation of Columns In Remarks, Section IV.

a. Column 7, Reference Code. The code recorded in column 6, Section II.
b. Column 2, Remarks. This column lists information pertinent to the maintenance function being performed as indicated in the MAC, Section II.

SECTION II MAINTENANCE ALLOCATION CHART
MULTIPLEXER, DIGITAL TD-1337(V)/G


## SECTION II MAINTENANCE ALLOCATION CHART <br> FOR <br> MULTIPLEXER, DIGITAL TD-1337(V)G

| (1) GROUP MUMBER | (2) COMPONENT/ASSEMBLY | (3) <br> MAINTEMANCE FUNCTION | (4) MAINTENANCE CATEGORY |  |  |  |  | (5) TOOLS AND EOPT. | (6) <br> REMARKS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | c | 0 | $F$ | H | D |  |  |
| 0201 | CIRCUIT CARD ASSY, DISPLAY$\text { SM-D-978510 }$ | REPLACE |  | 0.3 |  |  |  | $\begin{array}{\|l\|} \hline 9,10,14, \\ 16,52,54 \end{array}$ | k |
|  |  | REPAIR |  |  |  |  | 2.9 | $\begin{aligned} & 12.17, \\ & 42.45, \\ & 67.68, \\ & 70-72 \end{aligned}$ |  |
| 0202 | KEYBOARD ASSY | REPLACE |  | 0.7 |  |  |  | $\begin{aligned} & 9,10,14 \\ & 16,54 \end{aligned}$ | k |
|  |  | REPAIR |  |  | 0.2 |  |  | $\left\lvert\, \begin{aligned} & 1,17,46 . \\ & 49,64 \end{aligned}\right.$ |  |
| 03 | CIRCUIT CARD ASSY, M PROC (A) | REPLACE |  | 0.3 |  |  |  | 10,14 | A,k |
|  |  | REPAIR |  |  |  |  | 2.9 | $\left\|\begin{array}{l} 4,12,17 \\ 42,45,67 \\ 68,70-72 \end{array}\right\|$ |  |
| 04 | CIRCUIT CARD ASSY, NOM-VOLATILE MEMORY | Replace |  | 0.3 |  |  |  | 10,14 | A,K |
|  | SM-D-978555 | REPAIR |  |  |  |  | 2.9 | $\begin{aligned} & 4,12,17, \\ & 42,45, \\ & 67,68, \\ & 70-72 \end{aligned}$ |  |
| 05 | CIRCUIT CARD ASSY, SYNCHRONIZER \& SYNTHESIZER | REplace |  | 0.3 |  |  |  | 10,14 | A, K |
|  | SM-D-978560 | REPAIR |  |  |  |  | 2.9 | $\left\lvert\, \begin{aligned} & 4,11,12, \\ & 17,42, \\ & 45,67, \\ & 68,70-73 \end{aligned}\right.$ |  |
| 06 | CIRCUIT CARD ASSY, DEMUXSM-0-978565 | replace |  | 0.3 |  |  |  | 10,14 | A, K |
|  |  | repair |  |  |  |  | 2.9 | $\left\|\begin{array}{l} 4,11,12, \\ 17,42,45, \\ 67,68, \\ 70-72 \end{array}\right\|$ |  |
| 07 | CIRCUIT CARO ASSY, MUXSM-0-978570 | REPLACE |  | 0.3 |  |  |  | 10.14 | A,k |
|  |  | Repair |  |  |  |  | 2.9 | $\left\|\begin{array}{l} 4,12,17, \\ 42,45,67 \\ 68,70-72 \end{array}\right\|$ |  |
| OB | CIRCUIT CARD ASSY. Phase locked loop | REPLACE |  | 0.3 |  |  |  | 10.14 | A,k |
|  | SM-D-978575 | REPAIR |  |  |  |  | 2.9 | $\begin{aligned} & 2,4,11, \\ & 12,17,42, \\ & 45,67,68, \\ & 70-72 \end{aligned}$ |  |
| 09 | CIRCUIT CARD ASSY, 16 DVOWSM $-0-978585$ | REPLACE |  | 0.3 |  |  |  | 10,14 | A, K |
|  |  | REPAIR |  |  |  |  | 2.9 | $\left\|\begin{array}{l} 4,11,12, \\ 17,42,45, \\ 67,68, \\ 70-73 \end{array}\right\|$ |  |
| 10 | CIRCUIT CARD ASSY, LOOP HODEM/RATE MEASUREMENTSM-D-978590 | REPLACE |  | 0.3 |  |  |  | 10,14 | A, K, |
|  |  | REPAIR |  |  |  |  | 2.9 | $\begin{aligned} & 4,11,12, \\ & 17,42,45, \\ & 67,68, \\ & 70-73 \end{aligned}$ |  |
| 11 | Circuit card assy, mux input buffer | REPLACE |  | 0.3 |  |  |  | 10,14 | $A, K$ |
|  | SM-0-978595 | REPAIR |  |  |  |  | 2.9 | $\left\|\begin{array}{l} 4,12,17 \\ 42,45,67 \\ 58,70-72 \end{array}\right\|$ |  |

SECTION II MAINTENANCE ALLOCATION CHART
MULTIPLEXER, DIGITAL TD-1337(V)/G


SECTION III TOOL AND TEST EQUIPMENT REQUIREMENTS
MULITIPLEXER, DIGITAL TD-1337(V)/G


## SECTION III TOOL AND TEST EQURIPMENT REQUIREMENTS <br> MULTIPLEXER, DIGITAL TD-1337(V)/6



SECTION III TOOL AND TESST EQUIPMENT REQUIREMENTS
MULTIPLEXER, DIGITAL TD-1337VV)G



| REFERENCE CODE |  |  | MARKS |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| A | ASSEMBLY | T0-1337(V)1/6 | 10-1337(v)2/G | TD-1337(V)3/G | TD-1337(V)4/6 |
|  | POWER SUPPLY <br> 01 | X | $x$ | X | $x$ |
|  | PANEL ASSEMBLY, MUX CONTROL 02 | $x$ | x | $x$ | $\chi$ |
|  | $\begin{aligned} & \text { CIRCUIT CARD ASSY, M PROC (A) } \\ & 03 \end{aligned}$ | x | $\chi$ | - | - |
|  | CIRCUIT CARD ASSY, non-holatile memory 04 | $x$ | $x$ | x | $x$ |
|  | CIRCUIT CARD ASSY, SYNCHRONIZER 8 SYNTHESIZER 05 | $x$ | x | $x$ | $x$ |
|  | CIRCUIT CARD ASSY, DEMUX 06 | $X$ (4 REQ) | $X$ (1 REQ) | X (4 REQ) | X (1 REQ) |
|  | CIRCUIT CARD ASSY, MUX 07 | x | $x$ | x | $x$ |
|  | CIRCUIT CARD ASSY, PHASE LOCKED LOOP 08 | $x$ | $x$ | $\chi$ | x |
|  | CIRCUIT CARD ASSY, 16 DVOW 09 | $x$ | x | $x$ | $x$ |
|  | CIRCUIT CARD ASSY, <br> LOOP MODEM/RATE MEASUREMENT 10 | x | x | $x$ | x |
|  | CIRCUIT CARD ASSY, mXX INPUT BUFFER 11 | x | - | $x$ | x |
|  | CIRCUIT CARD ASSY, OUTPUT BUFFER | X (4 REQ) | X (1 REQ) | $x(4 \mathrm{REQ})$ | $x$ (2 REQ) |
|  | CIRCUIT CARO ASSY, GROUP MODEM 13 | x | $x$ | x | x |
|  | ${ }_{14}^{\text {CIRCUIT CARD ASSY, TD-660 I/O }}$ 14 | $x$ | $x$ | - | - |
|  | CASE ASSEMBLY, CARD FILE 15 | $x$ | $x$ | $x$ | x |
|  | BACKPLANE ASSY, WIRED 1501 | x | $x$ | $x$ | $x$ |
|  | $\begin{array}{\|l} \text { CASE ASSY } \\ 16 \end{array}$ | x | $x$ | x | $x$ |
|  | CABLE ASSY, WI 17 | x | X | x | $x$ |
|  | CABLE ASSY, W4 18 | X | - | $x$ | - |
|  | CABLE ASSY, W5 19 | x | - | - | - |
|  | CABLE ASSY, W6 20 | $x$ | x | - | - |


MULTPLEXER, DiGITALTD-1337(V)/G

| $\begin{aligned} & \text { REFERENCE } \\ & \text { CODE } \end{aligned}$ | REMARKS |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| A | ASSEMBLY $\quad$ TD-1337(V)1/G TD-1337(V)2/G TD-1337(V)3/G TD-1337(V)4/G |  |  |  |  |
|  | ${\underset{21}{\text { CABLE ASSY, W7 }}}^{\text {W }}$ | X | $x$ | X | X |
|  | $\begin{aligned} & \text { CABLE ASSY, W8 } \\ & 22 \end{aligned}$ | $x$ | X | $x$ | $x$ |
|  | CABLE ASSY, W9 23 | $x$ | $x$ | X | $x$ |
|  | $\begin{aligned} & \text { CABLE ASSY, WIO } \\ & 24 \end{aligned}$ | $x$ | $x$ | X | $x$ |
|  | ${ }_{25}^{\text {CABLE ASSY, W11 }}$ | $x$ | $x$ | X | X |
|  | RED CESE ASSY 26 | - | - | X | X |
|  | CIRCUIT CARD ASSY, RED CESE 2601 | - | - | $x$ | x |
|  | CIRCUIT CARD ASSY, 2.4 DVOW 27 | - | - | $x$ | x |
|  | CIRCUIT CARD ASSY, CESE STATUS COLLECTOR $28$ | - | - | X | X |
|  | CIRCUIT CARD ASSY, M PROC (B) 29 | - | - | x | X |
|  | $\begin{aligned} & \text { CABLE ASSY, W2 } \\ & 30 \end{aligned}$ |  | - | $\mathbf{x}$ | $x$ |
|  | $\left.\right\|_{31} ^{\text {CABLE ASSY, W3 }}$ |  | - | $\mathbf{X}$ | X |
| 8 | VISUAL ONLY |  |  |  |  |
| C | BUILT IN TEST PROCEDURES |  |  |  |  |
| D | REPAIR BY REPLACEMENT OF ASSEMB KEYBOARD (0202), OR COMPLETE END | $\begin{aligned} & \text { CO1, 0201, } 03 \\ & \text { FGC OO. } \end{aligned}$ | THRU 14, 26 THR | 29. INDICATOR | LAMPS, |
| E | REPAIR LIMITED TO REPAIR OF FGC COMPONENTS MOUNTED ON CHASSIS ( | THRU 25, 30, A | NO 31, AND REPL | ACEMENT OF SOME | MECHAMICAL |
| F | REPAIR IS LIMITED TO REPLACEMENT PART OF THE REPAIR ACTION OF FGC | $\text { C } 0201 \text { (CIRCUIT }$ ル TIPLEXER). | CARD) AND FGC | 0202 (KEYBOARD) | WHICH IS |
| G | REPAIR BY REPLACEMENT OF ALL EL | COMPONENTS. |  |  |  |
| H | REPAIR BY REPLACEMENT OF GASKET |  |  |  |  |
| I | ALL ADJUSTMENTS ARE PART OF REPA | ION OF POWER SUP | PPLY. |  |  |
| $J$ | REPLACEMENT OF POWER SUPPLY IS | REPAIR ACTION | OF MULTIPLEXER. |  |  |
| K | REPLACEMENT IS PART OF REPAIR AC | F MULTIPLEXER. |  |  |  |
| L | REPLACEMENT OF THIS UNIT IS PAR | R REPAIR ACTIONS | SPECIFIED IN | REMARKS D, E, A | D F. |
| M | REPLACEMENT OF THIS UNIT IS PART | R REPAIR ACTION | OF FGC 1501. |  |  |

## APPENDIX C EXPENDABLE SUPPLIES AND MATERIALS LIST

## Section I. INTRODUCTION

## C-1. scope.

This appendix lists expendable supplies and materials you will need to operate and maintain the TD-1337(V)/G. These items are authorized to you by CTA 50-970, Expendable Items (Except Medical, Class V, Repair Parts, and Heraldic Items).

## C-2. Explanation of Columns.

a. column (1) - Item Number. This number is assigned to the entry in the listing and is referenced in the narrative instructions to identify the material (e.g., "Use cleaning compound, item 5, App. D").
b. Column (2) - Level. This column identifies the lowest level of maintenance that requires the listed item.

C - Operator/Crew
0 - Organizational Maintenance
F - Direct Support Maintenance
H - General Support Maintenance
c. Column (3) - Nations/ Stock A/umber. This is the National stock number assigned to the item; use it to request or requisition the item.
d. Column (4) - Description. Indicates the Federal item name and, if required, a description to identify the item. The last line for each item indicates the Federal Supply Code for Manufacturer (FSCM) in parentheses followed by the part number.
e. Column (5) - Unit of Measure ( $U / M$ ). Indicates the measure used in performing the actual maintenance function. This measure is expressed by a two-character alphabetical abbreviation (e.g., ea, in., pr). If the unit of measure differs from the unit of issue, requisition the lowest unit of issue that will satisfy your requirements.

| (1) | (2) | (3) <br> ITEM <br> NUMBER | LEVEL | NATIONAL <br> STOCK <br> NUMBER |
| :---: | :---: | :---: | :---: | :---: |

## INDEX



## INDEX

| SUBJECT | Paragraph | Page |
| :---: | :---: | :---: |
| F |  |  |
| Features, characteristics, and capabilities | 1-9 | 1-5 |
| Front panel A23 |  |  |
| Block diagram discussion, part of |  |  |
| Multiplexer section for V1/V2 models | [-14 | -1-16 |
| Multiplexer section for V3/V4 models | [-16 | 1-20 |
| Removal and replacement instructions ................................................... [2-21 [2-42 |  |  |
| G |  |  |
| General information (See index on page 1-1.) |  |  |
| Group modem card A20 |  |  |
| Block diagram discussion, part of |  |  |
| Demultiplexer section for V1/V2 models. | 1-15 | (1-18 |
| Demultiplexer section for V3/V4 models. | [1-17 | -1-22 |
| Multiplexer section for V1/V2 models | [-14 | 1-16 |
| Multiplexer section for V3/V4 models | -1-16 | 1-20 |
| Replacement instructions .................................................................. [2-18 [2-36 |  |  |
| H |  |  |
| How to use |  |  |
| Alarms recall data | 2-14 | 2-22 |
| this manual. |  |  |
| I |  |  |
| Identification plates and stencils. | [1-11 | 1-10 |
| Inactive mode change troubleshooting .......................................................... 2-11 2-18 |  |  |
| Installation instructions (See index on page 2-31.) |  |  |
|  |  |  |
| Interface connector data. . . . . . | $\frac{2-4 \mid}{\frac{2-5}{2-5}}$ | $\frac{\frac{2-2}{[2-3]}}{[2]}$ |
| $J$ |  |  |
| J1 through J12 connectors, Signal-to-pin relationships .......................................... 2.5 [ ${ }^{\text {a-3 }}$ |  |  |
| K |  |  |
| Keyboard replacement instructions | [2-23] | 2-46 |
| L |  |  |
| List of abbreviations | 1-6 | 1-4 |
| Location and description of major components .....................................................1-10 [1-6 |  |  |
| Loop modem/rate measurement card A4 |  |  |
|  |  |  |
| Block diagram discussion, part of | 1-15 | 1-18 |
| Demultiplexer section for V3/V4 models......................................................... 1 -17 1 1-22 |  |  |
|  |  |  |
| Multiplexer section for V3/V4 models | [1-16 | [1-20 |
| Replacement instructions.................................................................. [2-18] [2-36] |  |  |

## INDEX

SUBJECT Paragraph Page
MMaintenance Allocation Chart (MAC)Explanation of columns in
MAC, Section II ..... B-3
Remarks, Section IV ..... B-5
Tools and Test Equipment Requirements, Section 111B-4
MAC (SectionB-2Maintenance functions, description of
Remarks table (Section IV) ..... IV)Tool and test equipment requirements (Section III)$1-3$Maintenance Forms, Records, and Reports
Maintenance Procedures
(See index on page 2-31.)
Major components, location and description o. ..... 1-10
Manual, type of ..... 1-1Model numbers and equipment name-1-1Microprocessor card Al 1Block diagram discussion, part ofMultiplexer section for V1/V2 models1-14
Multiplexer section for V3/V4 models ..... 1-16
Replacement instructions ..... 2-181-20
Multiplexer input buffer card A5
Block diagram discussion, part of
Multiplexer section for V1/V2 models ..... 1-14
Multiplexer section for V3/V4 models ..... 1-16
Replacement instructions ..... 2-182-38
Block diagram discussion, part of
Multiplexer section for V1/V2 models1-14
Multiplexer section for V3/V4 models ..... 1-16

Replacement instructions

Replacement instructions .....  ..... 2-18 .....  ..... 2-18 ..... 2-361-16
1-20
2-36
Multiplexer card A61-16
Multiplexer section block diagram discussions
V1/V2 models ..... 1-14 ..... 1-16
V3/V4 models ..... 1-16 ..... 1-20
N
Nomenclature, official. ..... 1-61-2
NVM (non-volatile memory/remote interface) card
Block diagram discussion, part of
Multiplexer section for V1/V2 models1-14
1-16
Multiplexer section for V3/V4 models. ..... 1-16 ..... 1-20
Replacement instructions ..... 2-18
2-36
NVM CHECKSUM ERROR troubleshooting ..... 2-10 ..... 2-16
0
Official nomenclature, names, and designations ..... 1-6
1-2
Operational test (TD-1337(V)/G) ..... 2-17
2-35
Output buffer cards A12 thru A15
Block diagram discussion, part of
Demultiplexer section for V1/V2 models1-15
Demultiplexer section for V3/V4 mdels ..... 1-17
Replacement instructions ..... 2-18 ..... 2-381-22

## INDEX

SUBJECT Paragraph ..... Page
P
Packaging r~uirements ..... 2-26 ..... 2-52
Phase locked loop (PLL) card A22
Block diagram discussion, part of
Demultiplexer section of V1/V2 models ..... 1-15
1-18
Demultiplexer section of V3/V4 models ..... 1-22
Multiplexer section of V1/V2 models ..... 1-14 ..... 1-16
Multiplexer section of V3/V4 models. ..... 1-16 ..... 1-20
Plug-in cardsPreparation for storage and shipment2-262-52
Replacement instructions ..... 2-18 ..... 2-36
POWER AC and DC indicator replacement instructions ..... 2-39
Power distribution troubleshooting ..... 2-20
Power requirements ..... 2-1
Power supply
Preparation for storage and shipment ..... 2-26 ..... 2-52
Replacement instructions ..... 2-40
Preparation for storage and shipment
(See index on page 2-52.)
Preventive Maintenance Checks and Services (PMCS) ..... 2-11
Principles of operation(See index on page 1-15.)
R
Rack mounting requirements ..... 2-1
Rear connector signal-to-pin relationships ..... 2-3
Red CESE Assembly A25
Part of block diagram discussion for multiplexer sections for V3/V4 models ..... 1-16 ..... 1-20
Replacement instmdions ..... 2-50
References ..... A-1
Reference designations ..... $1-2$
Repair Parts, Special Tools, TMDE, and Support Equipment ..... [1-1
Replacement and removal instructions
(See index on page 2-31.)
Reporting Equipment Improvement Recommendations (EIR's) ..... 1-4
S
Satellite side (Supergroup) interfaces ..... 1-13
Scope of manual ..... 1-1 ..... -1-1
Service upon receipt
(See index on page 2-1.)
Site and shelter requirements ..... 2-1
Special Tools, Repair Parts, TMDE, and Support Equipment ..... 1-2 ..... 1-1
Stencils and identification plates ..... 1-11
Storage or shipment, preparation for(See index on page 2-52.)

## INDEX

SUBJECT Paragraph ..... Page
Synchronizer/synthesizer/vinson buffer (SSV) card A2
Block diagram discussion, part of Demultiplexer section for V1/V2 models ..... 1-15 ..... 1-18
Demultiplexer section for V3/V4 models. ..... 1-14 ..... 1-16
Multiplexer section for V3/V4 models ..... 1-16 ..... 1-20
Replacement instructions ..... 2-36
T
TD-1337(V)/G
Connector data ..... 2-42-2
Operational test ..... 2-17 ..... 2-35
Principles of operation
(See index on page 1-15.)
Removal and installation instructions ..... 2-16 ..... 2-31
Service upon receipt
(See index on page 2-1.)
Troubleshooting
(See index on page 2-11.)
TD-660 I/O (660 I/O) card A3
Block diagram discussions, part of
Demultiplexer section of V1/V2 models ..... 1-15 1-18
Multiplexer section of V1/V2 models. ..... 1-14 ..... 1-16
Replacement instructions -18 ..... 2-36
Test, operational ..... 2-17
TMDE, Repair Parts, Special Tools and Support Equipment2-35
Tools and Test Equipment Requirements-1-1
Troubleshooting(See index on page 2-11.)
u
Unpacking equipment ..... 2-6
$16 \mathrm{~Kb} / \mathrm{s}$ digital voice orderwire (16 DVOW) card A7Block diagram discussion, part ofDemultiplexer section of V1/V2 models1-15 1-18
Demultiplexer section of V3/V4 models ..... 1-17 ..... 1-22
Multiplexer section of V1/V2 models ..... 1-14 ..... 1-16
Multiplexer section of V3/V4 models ..... 1-16 ..... 1-20
Replacement instructions ..... 2-16 ..... 2-36
$2.4 \mathrm{~Kb} /$ s digital voice orderwire (2.4 DVOW) card A8(Same references as for 16 DVOW card A7 above.)660 I/O card A3
(See TD-660 I/O card A3 above.)





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